

Operational Amplifiers / Comparators

High Speed with Low Voltage CMOS Operational Amplifiers

Input-Output Full Swing

BU7291G, BU7291SG, BU7255HFV, BU7255SHFV

Ground sense

BU7495HFV, BU7495SHFV, BU7481G, BU7481SG

BU7485G, BU7485SG, BU5281G, BU5281SG

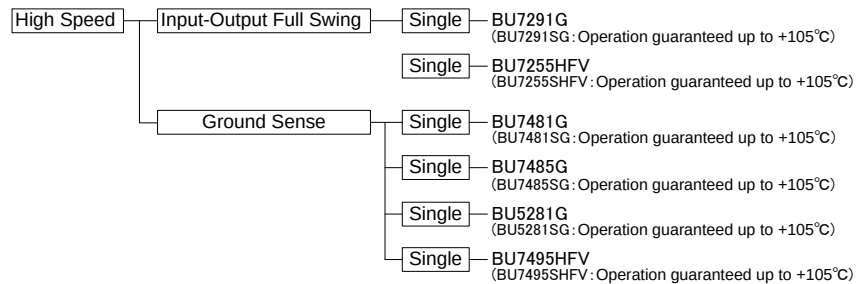


No.10049EAT20

Description

Low Voltage with High Speed CMOS Op-Amp integrates one independent output full swing Op-Amps and phase compensation capacitors on a single chip. Especially, this series is operable with low voltage, low supply current, high speed and low input bias current.

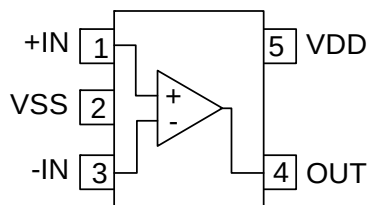
- Input-Output Full Swing
BU7291 family, BU7255 family
- Ground sense
BU7495 family, BU7481 family,
BU7485 family, BU5281 family



Features

- Low operating supply voltage
+2.4 [V] ~ +5.5 [V] (single supply): BU7291 family
BU7255 family
+1.8 [V] ~ +5.5 [V] (single supply): BU7495 family
BU7481 family
BU5281 family
+3.0 [V] ~ +5.5 [V] (single supply): BU7485 family
- High large signal voltage gain
- Internal ESD protection
Human body model (HBM) ± 4000 [V] (Typ.)
- Low input bias current 1[pA] (Typ.)
- High slew rate
3.0 [V/ μ s]: BU7291 family
3.4 [V/ μ s]: BU7255 family
5.0 [V/ μ s]: BU7495 family
3.2 [V/ μ s]: BU7481 family
2.0 [V/ μ s]: BU5281 family
10.0 [V/ μ s]: BU7485 family

Pin Assignments



SSOP5

BU7291G BU7291SG
BU7485G BU7485SG
BU7481G BU7481SG
BU5281G BU5281SG

HVSOF5

BU7255HFV BU7255SHFV
BU7495HFV BU7495SHFV

●Absolute Maximum Ratings(Ta=25[°C])

Parameter	Symbol	Ratings		Unit
		BU7291G, BU7255HFV BU7495HFV, BU7481G BU7485G, BU5281G	BU7291SG, BU7255SHFV BU7495SHFV, BU7481SG BU7485SG, BU5281SG	
Supply Voltage	VDD - VSS	+7		V
Differential Input Voltage ^(*1)	Vid	VDD - VSS		V
Input Common-mode Voltage Range	Vicm	(VSS - 0.3) ~ (VDD + 0.3)		V
Operating Temperature	Topr	- 40 ~ +85	- 40 ~ +105	°C
Storage Temperature	Tstg	- 55 ~ +125		°C
Maximum Junction Temperature	Tjmax	+125		°C

Note: Absolute maximum rating item indicates the condition which must not be exceeded.

Application of voltage in excess of absolute maximum rating or use out absolute maximum rated temperature environment may cause deterioration of characteristics.

(*1) The voltage difference between inverting input and non-inverting input is the differential input voltage. Then input terminal voltage is set to more than VSS.

●Electrical characteristics: Input-Output Full Swing

OBU7291 family(Unless otherwise specified VDD=+3[V], VSS=0[V], Ta=25[°C])

Parameter	Symbol	Temperature Range	Limits			Unit	Condition
			BU7291G, BU7291SG				
			Min.	Typ.	Max.		
Input Offset Voltage ^(*2)	Vio	25°C	—	1	9	mV	—
Input Offset Current ^(*2)	Iio	25°C	—	1	—	pA	—
Input Bias Current ^(*2)	Ib	25°C	—	1	—	pA	—
Supply Current ^(*3)	IDD	25°C	—	470	800	μA	RL=∞ All Op-Amps AV=0[dB], VIN=1.5[V]
		Full range	-	—	1100		
High Level Output Voltage	VOH	25°C	VDD-0.1	—	—	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25°C	—	—	VSS+0.1	V	RL=10[kΩ]
Large Signal Voltage Gain	AV	25°C	70	105	—	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25°C	0	—	3	V	VSS ~ VDD
Common-mode Rejection Ratio	CMRR	25°C	40	60	—	dB	—
Power Supply Rejection Ratio	PSRR	25°C	45	80	—	dB	—
Output Source Current ^(*4)	IOH	25°C	5	8	—	mA	VDD-0.4[V]
Output Sink Current ^(*4)	IOL	25°C	9	16	—	mA	VSS+0.4[V]
Slew Rate	SR	25°C	—	3.0	—	V/μs	CL=25[pF]
Gain Band width	FT	25°C	—	2.8	—	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25°C	—	50	—	°	CL=25[pF], AV=40[dB]
Total Harmonic Distortion	THD	25°C	—	0.03	—	%	VOUT=0.8[Vp-p], f=1[kHz]

(*2) Absolute value

(*3) Full range BU7291: Ta=-40[°C]~+85[°C] BU7291S: Ta=-40[°C]~+105[°C]

(*4) Under the high temperature environment, consider the power dissipation of IC when selecting the output current.

When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.

OBU7255(Unless otherwise specified VDD=+3[V], VSS=0[V], Ta=25[°C])

Parameter	Symbol	Temperature Range	Limits			Unit	Condition
			BU7255HFV, BU7255SHFV				
			Min.	Typ.	Max.		
Input Offset Voltage ^(*5)	Vio	25°C	—	1	9	mV	—
Input Offset Current ^(*5)	Iio	25°C	—	1	—	pA	—
Input Bias Current ^(*5)	Ib	25°C	—	1	—	pA	—
Supply Current ^(*6)	IDD	25°C	—	540	900	μA	RL=∞ All Op-Amps AV=0[dB], VIN=1.5[V]
		Full range	—	—	1200		
High Level Output Voltage	VOH	25°C	VDD-0.1	—	—	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25°C	—	—	VSS+0.1	V	RL=10[kΩ]
Large Signal Voltage Gain	AV	25°C	60	105	—	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25°C	0	-	3	V	VSS ~ VDD
Common-mode Rejection Ratio	CMRR	25°C	40	60	—	dB	—
Power Supply Rejection Ratio	PSRR	25°C	45	80	—	dB	—
Output Source Current ^(*7)	IOH	25°C	2	4	—	mA	VDD - 0.4[V]
Output Sink Current ^(*7)	IOL	25°C	4	8	—	mA	VSS + 0.4[V]
Slew Rate	SR	25°C	—	3.4	—	V/μs	CL=25[pF]
Gain Band width	FT	25°C	—	4	—	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25°C	—	40	—	°	CL=25[pF], AV=40[dB]

(*5) Absolute value

(*6) Full range BU7255: Ta=-40[°C]~+85[°C] BU7255S: Ta=-40[°C]~+105[°C]

(*7) Under the high temperature environment, consider the power dissipation of IC when selecting the output current.

When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.

OBU7495 family(Unless otherwise specified VDD=+3[V], VSS=0[V], Ta=25[°C])

Parameter	Symbol	Temperature Range	Limits			Unit	Condition
			BU7495HFV, BU7495SHFV				
			Min.	Typ.	Max.		
Input Offset Voltage ^(*8)	Vio	25°C	—	1	6	mV	—
Input Offset Current ^(*8)	Iio	25°C	—	1	—	pA	—
Input Bias Current ^(*8)	Ib	25°C	—	1	—	pA	—
Supply Current ^(*9)	IDD	25°C	—	650	1150	μA	RL=∞ All Op-Amps AV=0[dB], VIN=0.9[V]
		Full range	—	—	1350		
High Level Output Voltage	VOH	25°C	VDD-0.1	—	—	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25°C	-	-	VSS+0.1	V	RL=10[kΩ]
Large Signal Voltage Gain	AV	25°C	60	100	—	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25°C	0	-	1.8	V	VSS ~ VDD-1.2[V]
Common-mode Rejection Ratio	CMRR	25°C	45	60	—	dB	—
Power Supply Rejection Ratio	PSRR	25°C	60	80	—	dB	—
Output Source Current ^(*10)	IOH	25°C	4	7	—	mA	VDD - 0.4[V]
Output Sink Current ^(*10)	IOL	25°C	9	14	—	mA	VSS + 0.4[V]
Slew Rate	SR	25°C	—	5.0	—	V/μs	CL=25[pF]
Gain Band width	FT	25°C	—	4	—	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25°C	—	50	—	°	CL=25[pF], AV=40[dB]
Total Harmonic Distortion	THD	25°C	—	0.03	—	%	VOUT=0.8[Vp-p], f=1[kHz]

(*8) Absolute value

(*9) Full range BU7495: Ta=-40[°C]~+85[°C] BU7495S: Ta=-40[°C]~+105[°C]

(*10) Under the high temperature environment, consider the power dissipation of IC when selecting the output current.

When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC

OBU7481 family(Unless otherwise specified VDD=+3[V], VSS=0[V], Ta=25[°C])

Parameter	Symbol	Temperature Range	Limits			Unit	Condition
			BU7481G, BU7481SG				
			Min.	Typ.	Max.		
Input Offset Voltage ^(*11)	Vio	25°C	—	1	8	mV	—
Input Offset Current ^(*11)	Iio	25°C	—	1	—	pA	—
Input Bias Current ^(*11)	Ib	25°C	—	1	—	pA	—
Supply Current ^(*12)	IDD	25°C	—	420	750	μA	RL=∞ All Op-Amps AV=0[dB], VIN=0.9[V]
		Full range	—	—	900		
High Level Output Voltage	VOH	25°C	VDD-0.1	—	—	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25°C	—	—	VSS+0.1	V	RL=10[kΩ]
Large Signal Voltage Gain	AV	25°C	70	105	—	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25°C	0	—	1.8	V	VSS ~ VDD-1.2[V]
Common-mode Rejection Ratio	CMRR	25°C	45	60	—	dB	—
Power Supply Rejection Ratio	PSRR	25°C	60	80	—	dB	—
Output Source Current ^(*13)	IOH	25°C	5	8	—	mA	VDD - 0.4[V]
Output Sink Current ^(*13)	IOL	25°C	9	16	—	mA	VSS + 0.4[V]
Slew Rate	SR	25°C	—	3.2	—	V/μs	CL=25[pF]
Gain Band width	FT	25°C	—	2.8	—	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25°C	—	50	—	°	CL=25[pF], AV=40[dB]
Total Harmonic Distortion	THD	25°C	—	0.03	—	%	VOUT=0.8[Vp-p], f=1[kHz]

(*11) Absolute value

(*12) Full range BU7481: Ta=-40[°C]~+85[°C] BU7481S: Ta=-40[°C]~+105[°C]

(*13) Under the high temperature environment, consider the power dissipation of IC when selecting the output current.

When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.

OBU7485 family(Unless otherwise specified VDD=+3[V], VSS=0[V], Ta=25[°C])

Parameter	Symbol	Temperature Range	Limits			Unit	Condition
			BU7485G, BU7485SG				
			Min.	Typ.	Max.		
Input Offset Voltage ^(*14)	Vio	25°C	—	1	9.5	mV	—
Input Offset Current ^(*14)	Iio	25°C	—	1	—	pA	—
Input Bias Current ^(*14)	Ib	25°C	—	1	—	pA	—
Supply Current ^(*15)	IDD	25°C	—	1500	2000	μA	RL=∞ All Op-Amps AV=0[dB], VIN=0.8[V]
		Full range	—	—	2400		
High Level Output Voltage	VOH	25°C	VDD-0.1	—	—	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25°C	—	—	VSS+0.1	V	RL=10[kΩ]
Large Signal Voltage Gain	AV	25°C	70	105	—	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25°C	0	—	1.6	V	VSS ~ VDD-1.4[V]
Common-mode Rejection Ratio	CMRR	25°C	45	60	—	dB	—
Power Supply Rejection Ratio	PSRR	25°C	60	80	—	dB	—
Output Source Current ^(*16)	IOH	25°C	4	8	—	mA	VDD-0.4[V]
Output Sink Current ^(*16)	IOL	25°C	7	12	—	mA	VSS + 0.4[V]
Slew Rate	SR	25°C	—	10	—	V/μs	CL=25[pF]
Gain Band width	FT	25°C	—	10	—	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25°C	—	50	—	°	CL=25[pF], AV=40[dB]
Total Harmonic Distortion	THD	25°C	—	0.03	—	%	VOUT=0.7[Vp-p], f=1[kHz]

(*14) Absolute value

(*15) Full range BU7485: Ta=-40[°C]~+85[°C] BU7485S: Ta=-40[°C]~+105[°C]

(*16) Under the high temperature environment, consider the power dissipation of IC when selecting the output current.

When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.

OBU5281 family(Unless otherwise specified VDD=+3[V], VSS=0[V], Ta=25[°C])

Parameter	Symbol	Temperature Range	Limits			Unit	Condition
			BU5281G, BU5281SG				
			Min.	Typ.	Max.		
Input Offset Voltage ^(*17)	Vio	25°C	—	0.1	2.5	mV	—
Input Offset Voltage drift ^(*17)	ΔVio/ΔT	-	—	0.8	—	μV/°C	—
Input Offset Current ^(*17)	Iio	25°C	—	1	—	pA	—
Input Bias Current ^(*17)	Ib	25°C	—	1	—	pA	—
Supply Current ^(*18)	IDD	25°C	—	750	1000	μA	RL=∞ All Op-Amps AV=0[dB], VIN=0.9[V]
		Full range	—	—	1200		
High Level Output Voltage	VOH	25°C	VDD-0.1	—	—	V	RL=10[kΩ]
Low Level Output Voltage	VOL	25°C	—	—	VSS+0.1	V	RL=10[kΩ]
Large Signal Voltage Gain	AV	25°C	70	110	—	dB	RL=10[kΩ]
Input Common-mode Voltage Range	Vicm	25°C	0	—	1.8	V	VSS ~ VDD - 1.2[V]
Common-mode Rejection Ratio	CMRR	25°C	45	60	—	dB	—
Power Supply Rejection Ratio	PSRR	25°C	60	80	—	dB	—
Output Source Current ^(*19)	IOH	25°C	5	8	—	mA	VDD-0.4[V]
Output Sink Current ^(*19)	IOL	25°C	10	16	—	mA	VSS+0.4[V]
Slew Rate	SR	25°C	—	2.0	—	V/μs	CL=25[pF]
Gain Band width	FT	25°C	—	3	—	MHz	CL=25[pF], AV=40[dB]
Phase Margin	θ	25°C	—	40	—	°	CL=25[pF], AV=40[dB]
Input Referred Noise Voltage	Vin	25°C	—	18	—	nV/(Hz) ^{1/2}	AV=40[dB], f=1[kHz]
			—	3.2	—	μVrms	AV=40[dB], DINAUDIO
Total Harmonic Distortion	THD	25°C	—	0.003	—	%	VOUT=0.4[Vp-p], f=1[kHz]

(*17) Absolute value

(*18) Full range BU5281: Ta=-40[°C]~+85[°C] BU5281S: Ta=-40[°C]~+105[°C]

(*19) Under the high temperature environment, consider the power dissipation of IC when selecting the output current.

When the terminal short circuits are continuously output, the output current is reduced to climb to the temperature inside IC.

●Reference Data (BU7291 family)

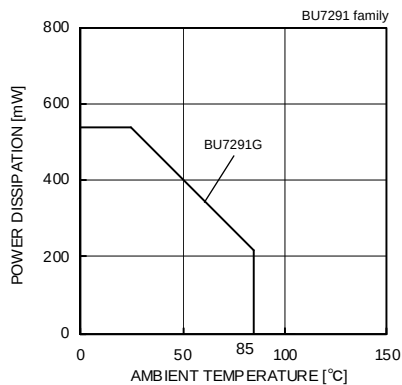


Fig.1
Derating curve

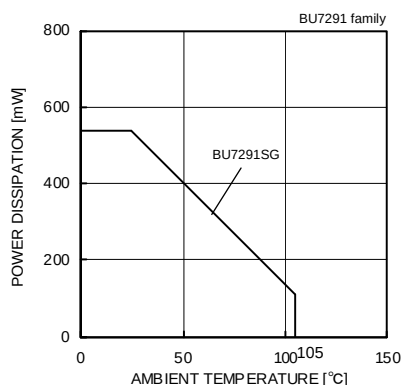


Fig.2
Derating curve

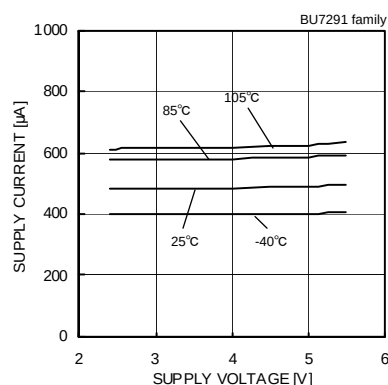


Fig.3
Supply Current – Supply Voltage

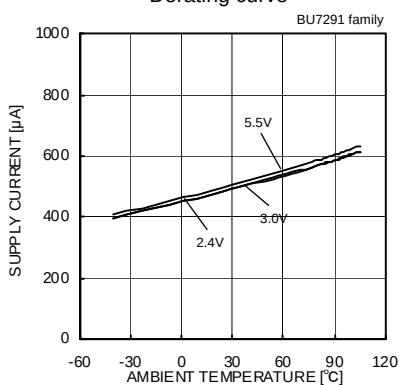


Fig.4
Supply Current
– Ambient Temperature

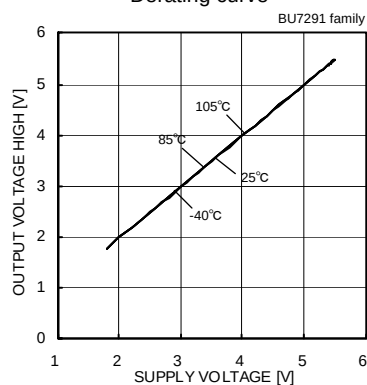


Fig.5
Output Voltage High
– Supply Voltage (RL=10[kΩ])

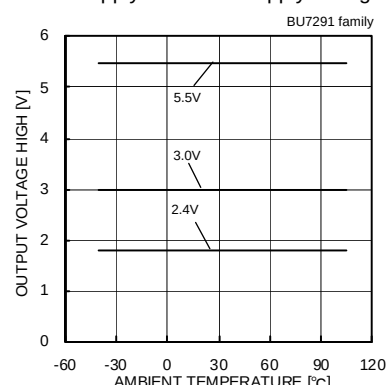


Fig.6
Output Voltage High
– Ambient Temperature (RL=10[kΩ])

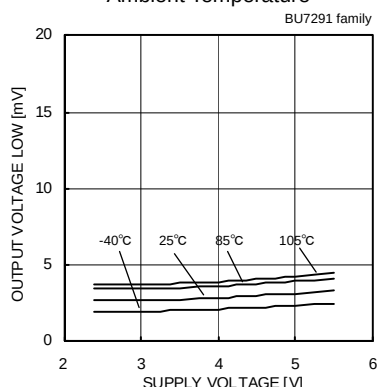


Fig.7
Output Voltage Low
– Supply Voltage (RL=10[kΩ])

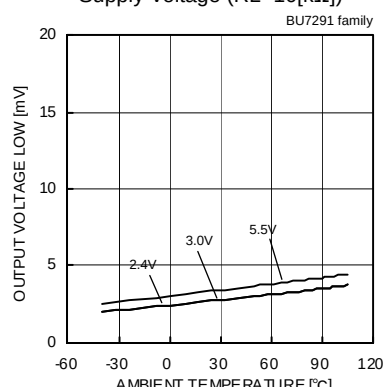


Fig.8
Output Voltage Low
– Ambient Temperature (RL=10[kΩ])

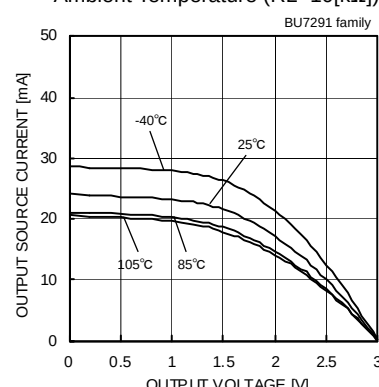


Fig.9
Output Source Current
– Output Voltage (VDD=3[V])

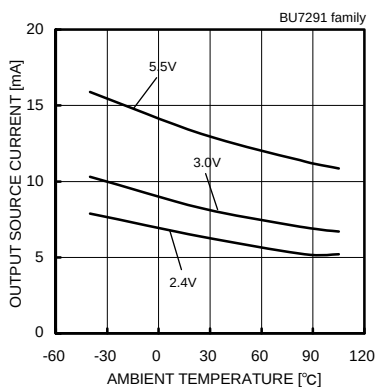


Fig.10
Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

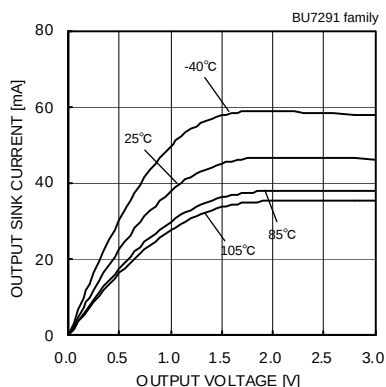


Fig.11
Output Sink Current – Output Voltage
(VDD=3[V])

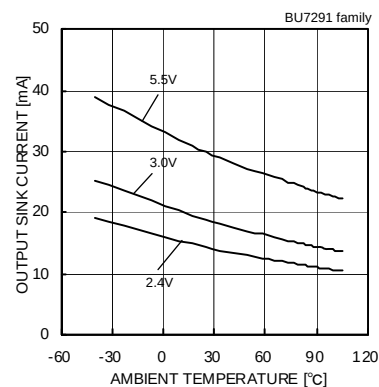


Fig.12
Output Sink Current – Ambient Temperature
(VOUT=VSS+0.4[V])

(*)The above data is ability value of sample, it is not guaranteed. BU7291G: -40[°C] ~ +85[°C] BU7291SG: -40[°C] ~ +105[°C]

●Reference Data (BU7291 family)

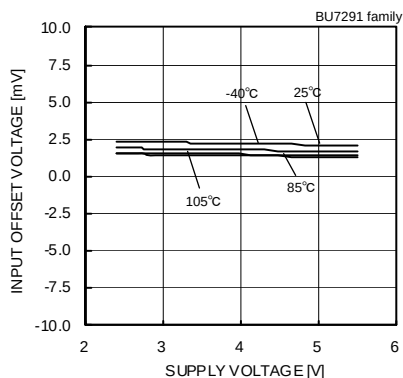


Fig.13
Input Offset Voltage – Supply Voltage
($V_{icm}=V_{DD}$, $V_{OUT}=1.5[V]$)

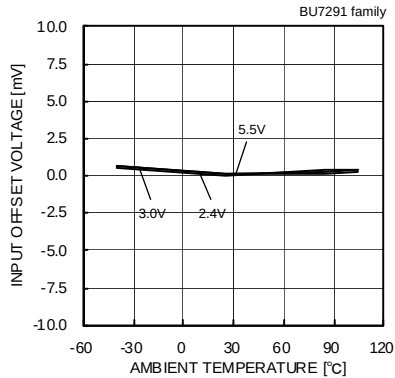


Fig.14
Input Offset Voltage – Ambient Temperature
($V_{icm}=V_{DD}$, $V_{OUT}=1.5[V]$)

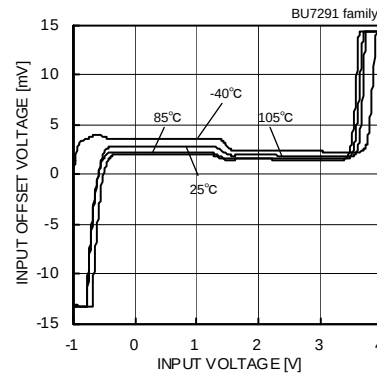


Fig.15
Input Offset Voltage – Input Voltage
($V_{DD}=3[V]$)

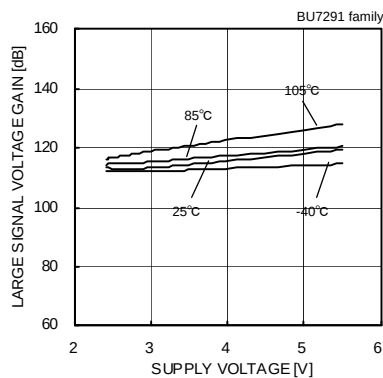


Fig.16
Large Signal Voltage Gain
– Supply Voltage

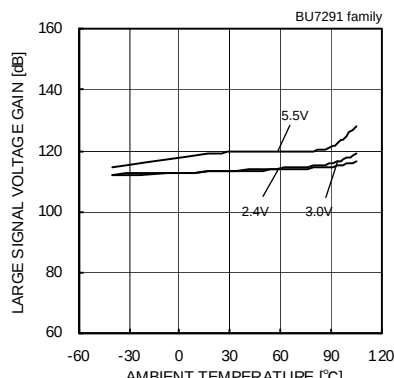


Fig.17
Large Signal Voltage Gain
– Ambient Temperature

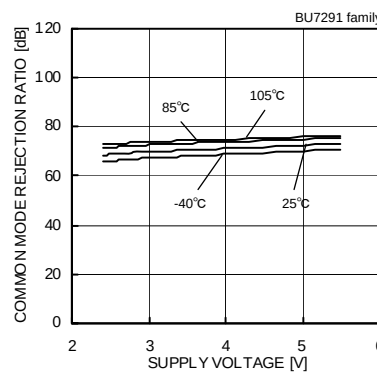


Fig.18
Common Mode Rejection Ratio
– Supply Voltage ($V_{DD}=3[V]$)

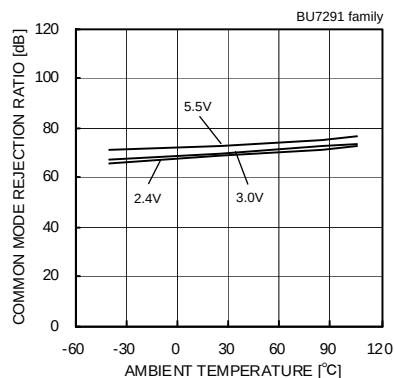


Fig.19
Common Mode Rejection Ratio
– Ambient Temperature

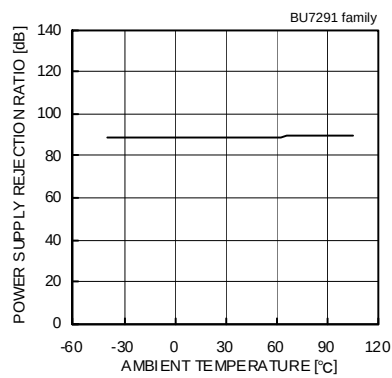


Fig.20
Power Supply Rejection Ratio
– Ambient Temperature

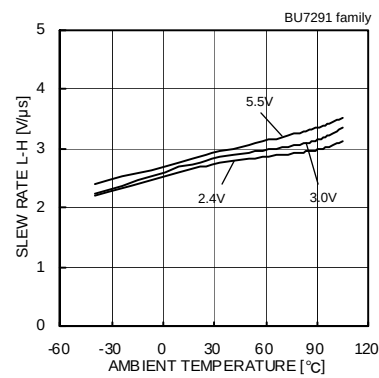


Fig.21
Slew Rate L-H
– Ambient Temperature

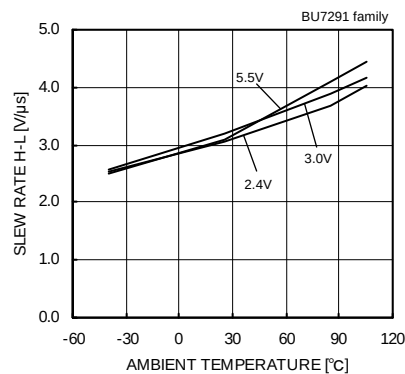


Fig.22
Slew Rate H-L – Ambient Temperature

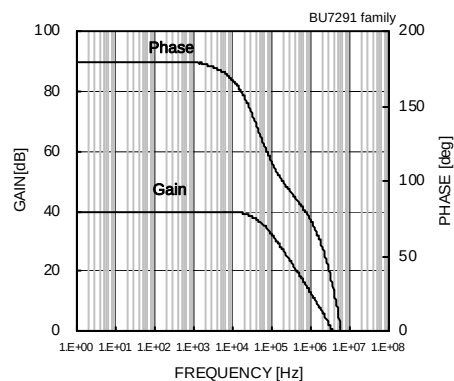


Fig.23
Voltage Gain – Frequency

(*)The above data is ability value of sample, it is not guaranteed. BU7291G: -40[°C] ~ +85[°C] BU7291SG: -40[°C] ~ +105[°C]

●Reference Data (BU7255 family)

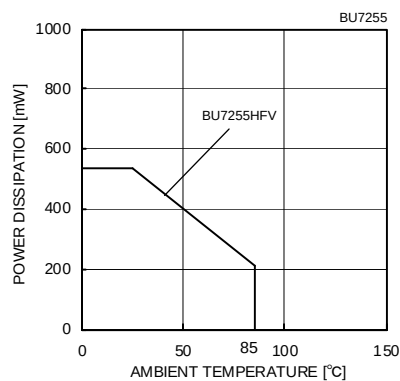


Fig.24
Derating curve

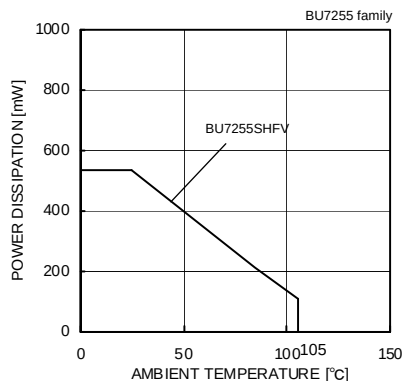


Fig.25
Derating curve

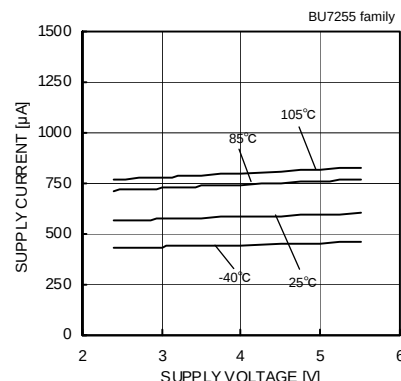


Fig.26
Supply Current – Supply Voltage

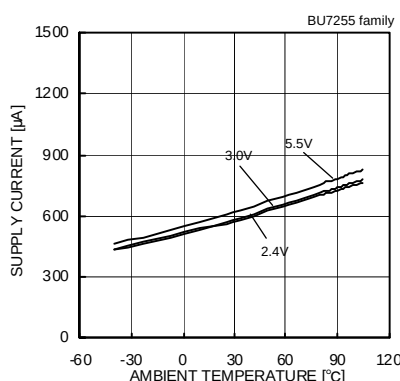


Fig.27
Supply Current
– Ambient Temperature

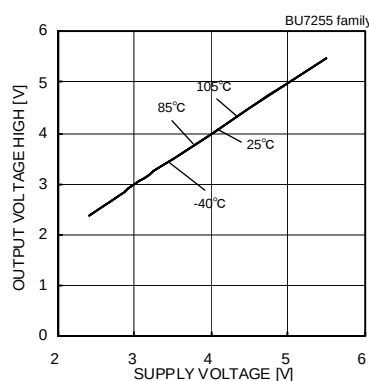


Fig.28
Output Voltage High
– Supply Voltage (RL=10[kΩ])

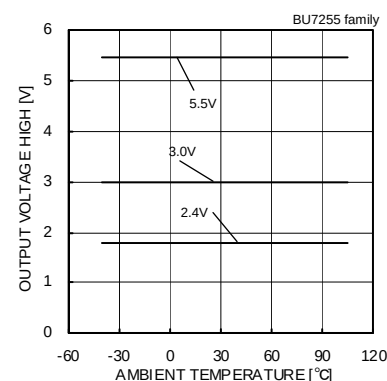


Fig.29
Output Voltage High
– Ambient Temperature (RL=10[kΩ])

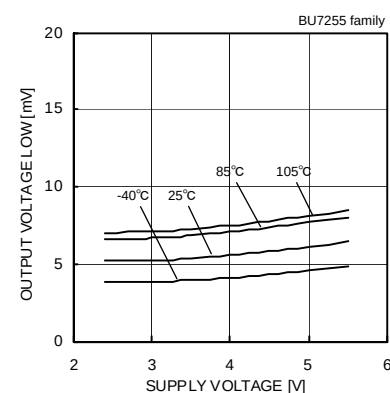


Fig.30
Output Voltage Low
– Supply Voltage (RL=10[kΩ])

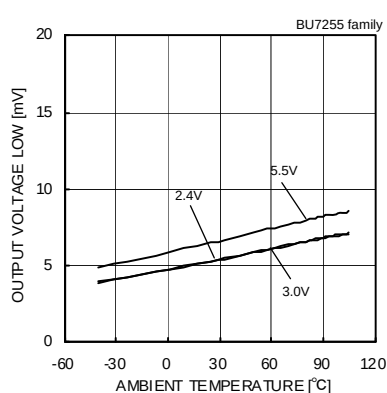


Fig.31
Output Voltage Low
– Ambient Temperature (RL=10[kΩ])

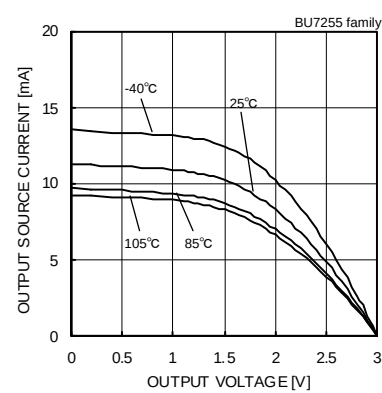


Fig.32
Output Source Current
– Output Voltage (VDD=3[V])

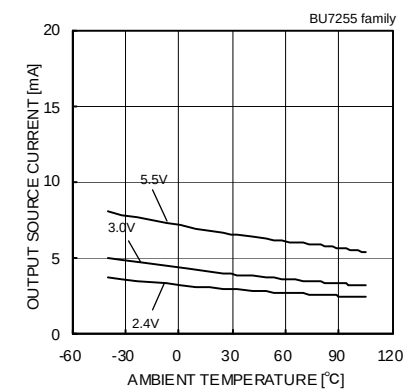


Fig.33
Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

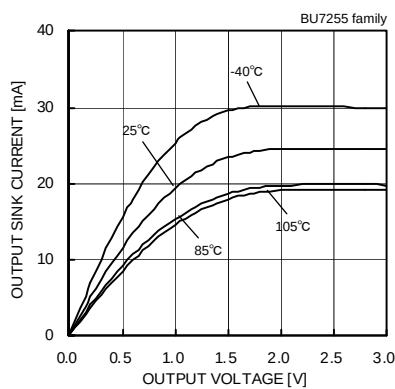


Fig.34
Output Sink Current – Output Voltage
(VDD=3[V])

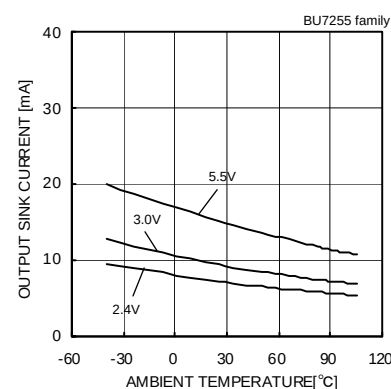


Fig.35
Output Sink Current – Ambient Temperature
(VOUT=VSS+0.4[V])

(*)The above data is ability value of sample, it is not guaranteed. BU7255HFV: -40[°C] ~ +85[°C] BU7255SHFV: -40[°C] ~ +105[°C]

●Reference Data (BU7255 family)

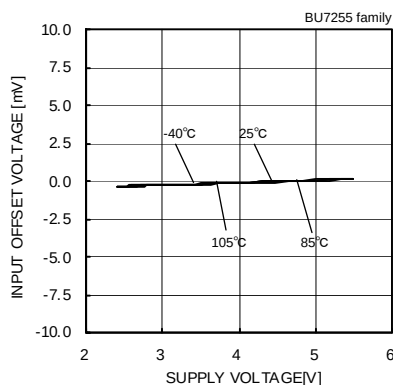


Fig.36

Input Offset Voltage – Supply Voltage
($V_{cm}=V_{DD}$, $V_{OUT}=1.5[V]$)

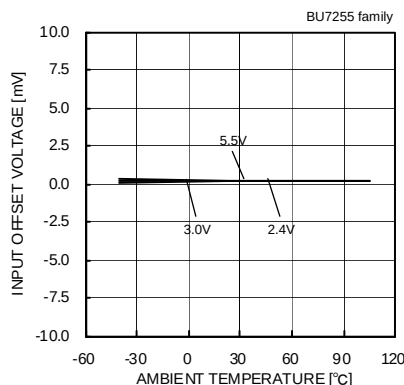


Fig.37

Input Offset Voltage – Ambient Temperature
($V_{cm}=V_{DD}$, $V_{OUT}=1.5[V]$)

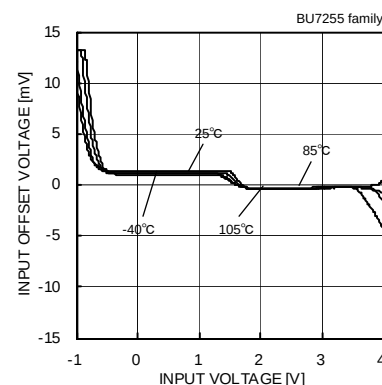


Fig.38

Input Offset Voltage – Input Voltage
($V_{DD}=3[V]$)

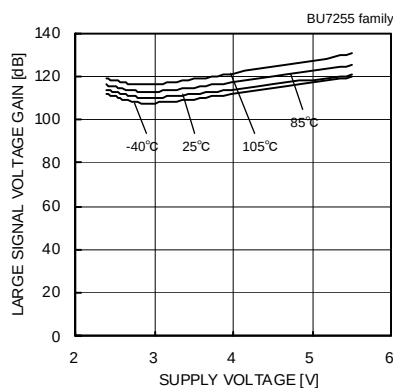


Fig.39

Large Signal Voltage Gain
– Supply Voltage

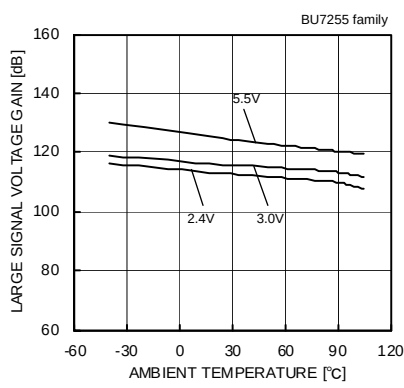


Fig.40

Large Signal Voltage Gain
– Ambient Temperature

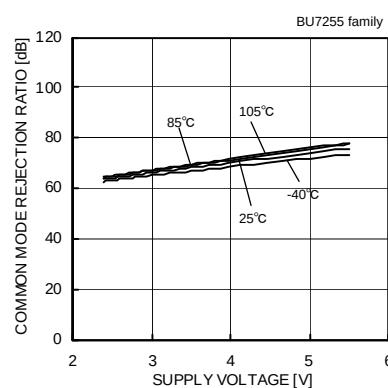


Fig.41

Common Mode Rejection Ratio
– Supply Voltage ($V_{DD}=3[V]$)

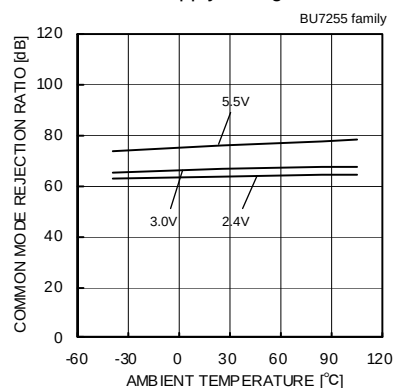


Fig.42

Common Mode Rejection Ratio
– Ambient Temperature

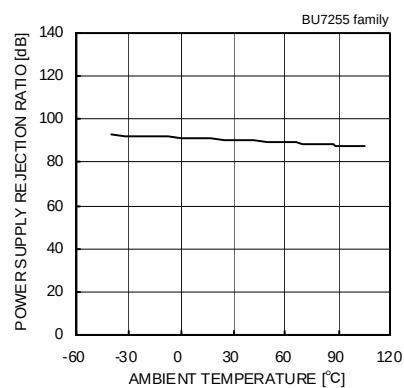


Fig.43

Power Supply Rejection Ratio
– Ambient Temperature

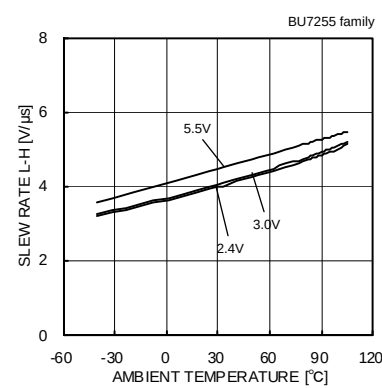


Fig.44

Slew Rate L-H
– Ambient Temperature

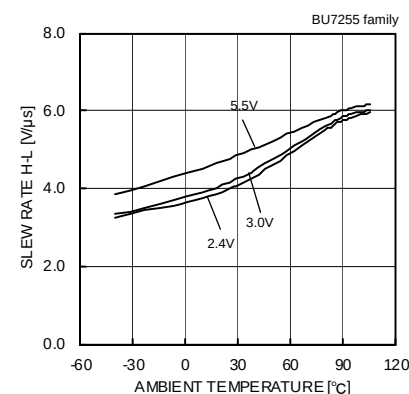


Fig.45

Slew Rate H-L – Ambient Temperature

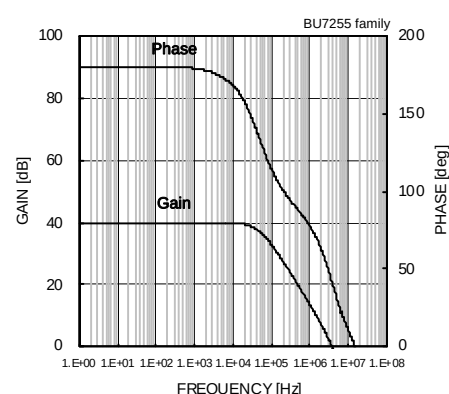


Fig.46

Voltage Gain – Frequency

(*)The above data is ability value of sample, it is not guaranteed. BU7255HFV: -40[°C] ~ +85[°C] BU7255SHFV: -40[°C] ~ +105[°C]

●Reference Data (BU7495 family)

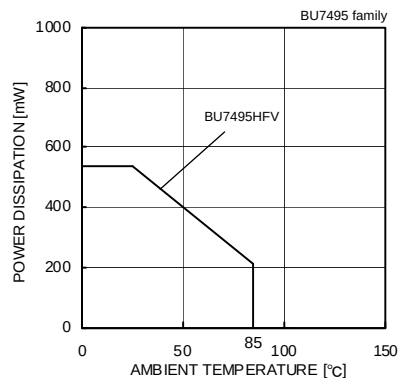


Fig.47

Derating curve

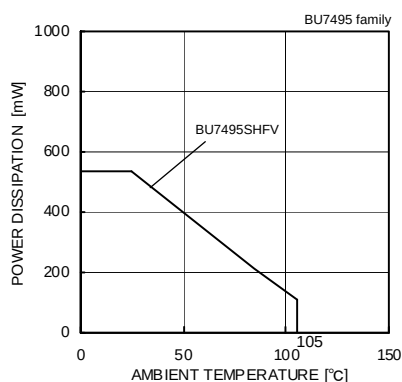


Fig.48

Derating curve

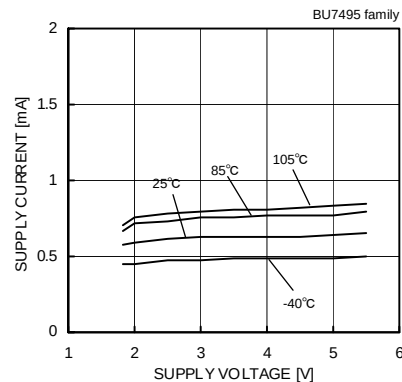


Fig.49

Supply Current – Supply Voltage

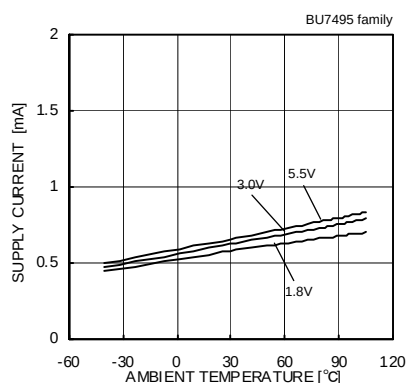


Fig.50

Supply Current
– Ambient Temperature

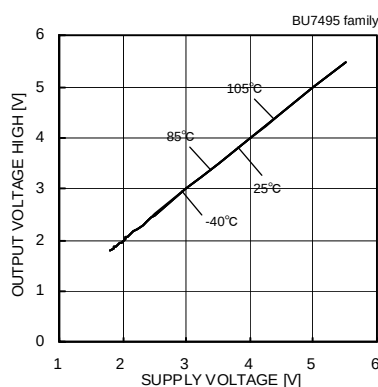


Fig.51

Output Voltage High
– Supply Voltage (RL=10[kΩ])

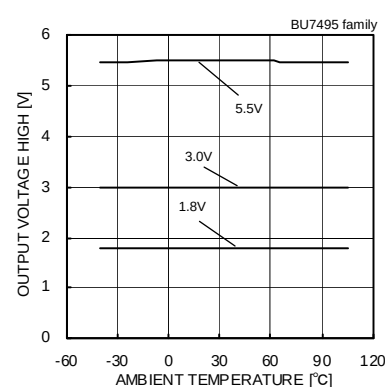


Fig.52

Output Voltage High
– Ambient Temperature (RL=10[kΩ])

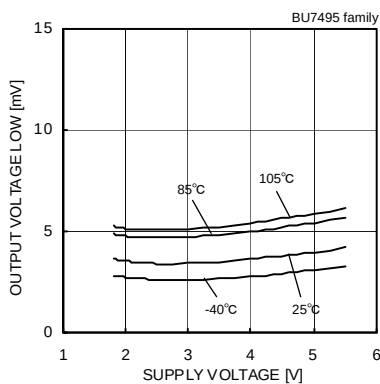


Fig.53

Output Voltage Low
– Supply Voltage (RL=10[kΩ])

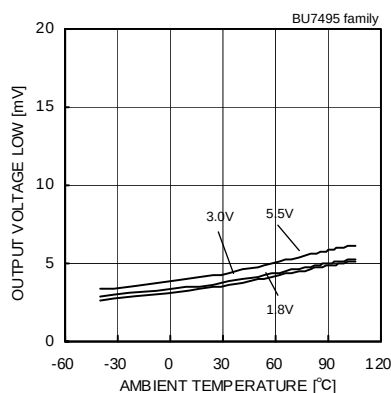


Fig.54

Output Voltage Low – Ambient
Temperature (RL=10[kΩ])

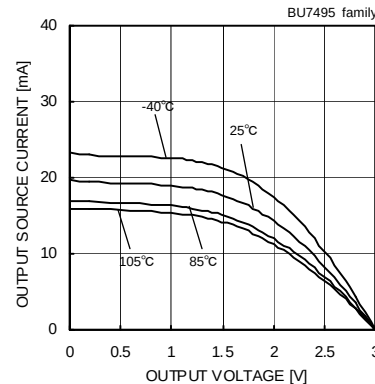


Fig.55

Output Source Current – Output
Voltage (VDD=3[V])

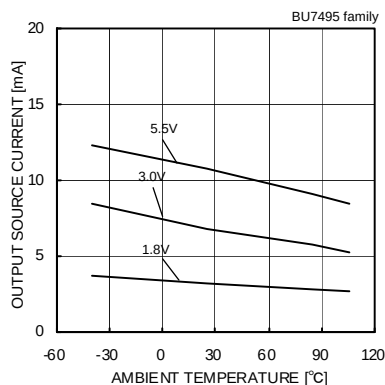


Fig.56

Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

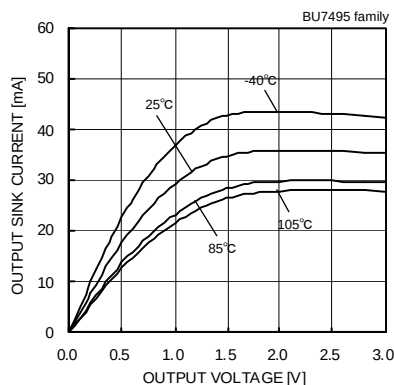


Fig.57

Output Sink Current – Output Voltage
(VDD=3[V])

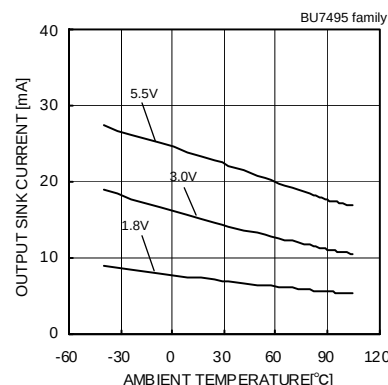


Fig.58

Output Sink Current – Ambient Temperature
(VOUT=VSS+0.4[V])

(*)The above data is ability value of sample, it is not guaranteed. BU7495HFV: -40[°C] ~ +85[°C] BU7495SHFV: -40[°C] ~ +105[°C]

●Reference Data (BU7495 family)

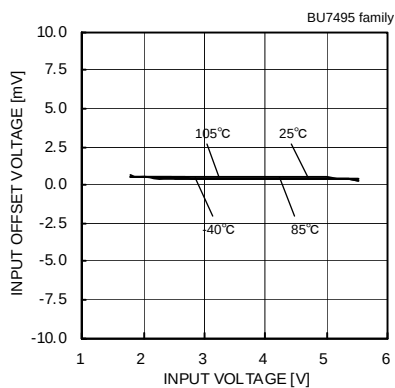


Fig.59
Input Offset Voltage – Supply Voltage
($V_{icm}=V_{DD}-1.2[V]$, $V_{OUT}=1.5[V]$)

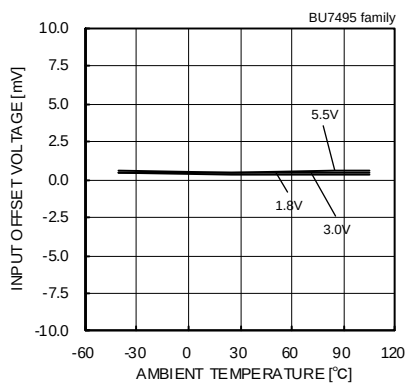


Fig.60
Input Offset Voltage – Ambient Temperature
($V_{icm}=V_{DD}$, $V_{OUT}=1.5[V]$)

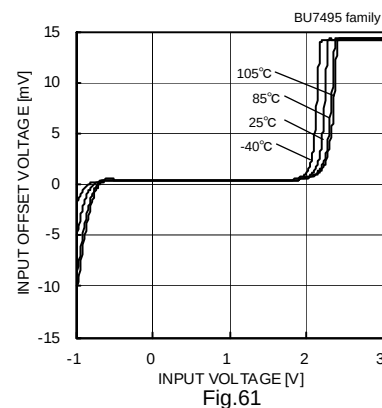


Fig.61
Input Offset Voltage – Input Voltage
($V_{DD}=3[V]$)

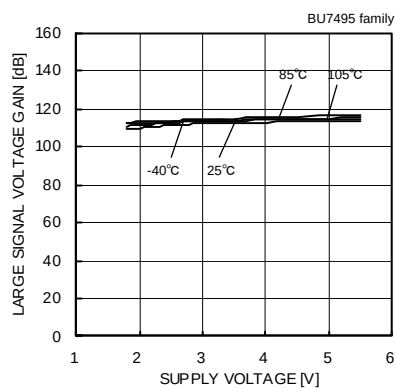


Fig.62
Large Signal Voltage Gain
– Supply Voltage

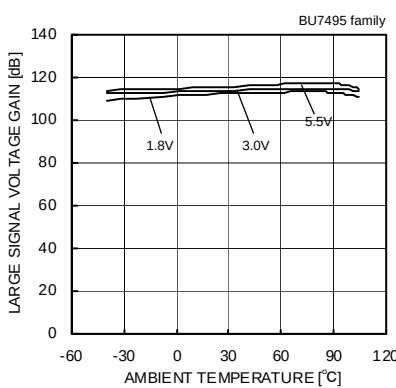


Fig.63
Large Signal Voltage Gain
– Ambient Temperature

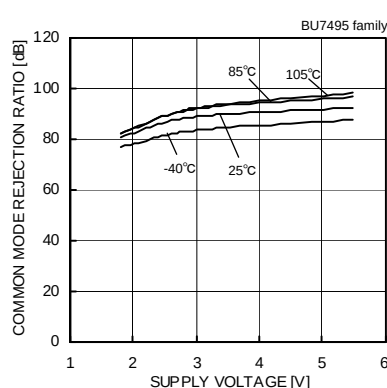


Fig.64
Common Mode Rejection Ratio
– Supply Voltage ($V_{DD}=3[V]$)

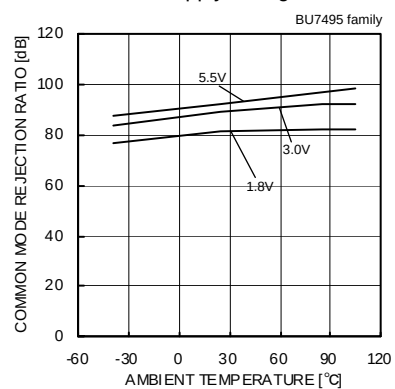


Fig.65
Common Mode Rejection Ratio
– Ambient Temperature

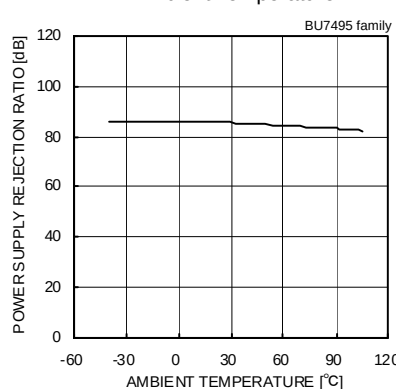


Fig.66
Power Supply Rejection Ratio
– Ambient Temperature

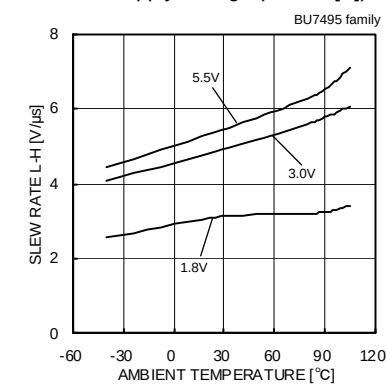


Fig.67
Slew Rate L-H
– Ambient Temperature

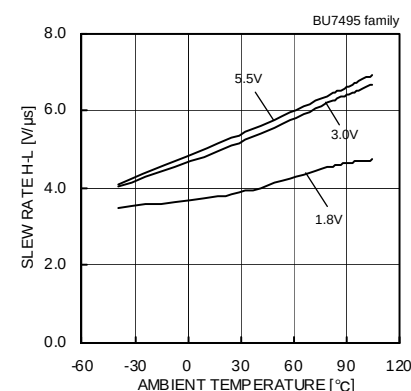


Fig.68
Slew Rate H-L – Ambient Temperature

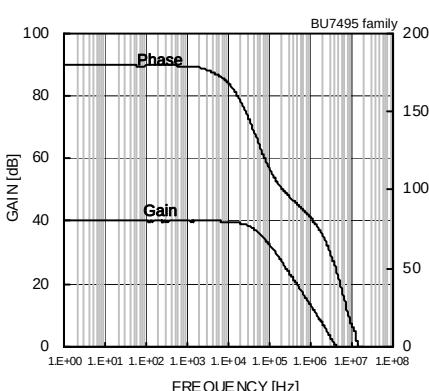


Fig.69
Voltage Gain – Frequency

(*)The above data is ability value of sample, it is not guaranteed. BU7495HFV: -40[°C] ~ +85[°C] BU7495SHFV: -40[°C] ~ +105[°C]

●Reference Data (BU7481 family)

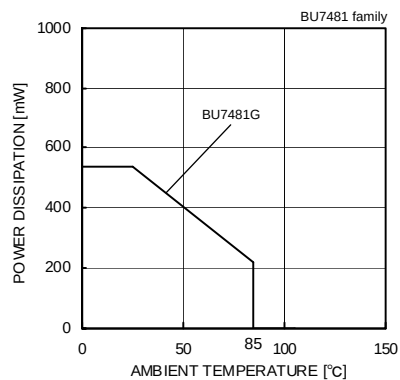


Fig.70
Derating curve

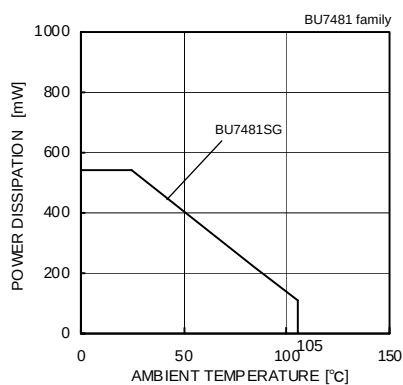


Fig.71
Derating curve

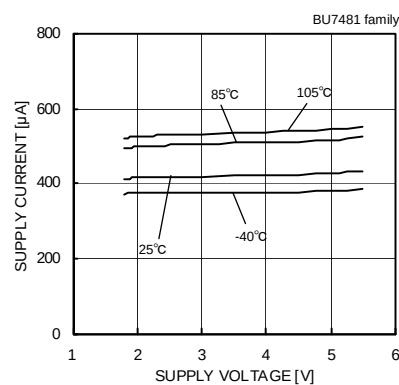


Fig.72
Supply Current – Supply Voltage

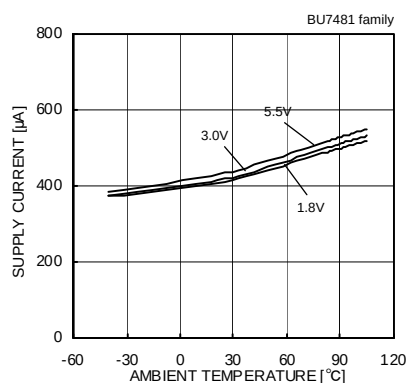


Fig.73
Supply Current
– Ambient Temperature

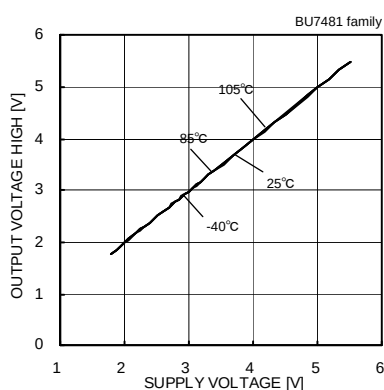


Fig.74
Output Voltage High
– Supply Voltage (RL=10[kΩ])

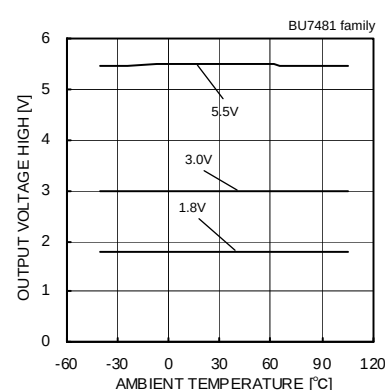


Fig.75
Output Voltage High
– Ambient Temperature (RL=10[kΩ])

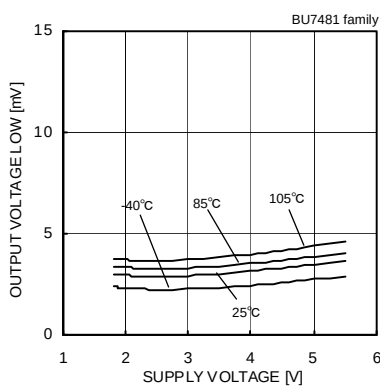


Fig.76
Output Voltage Low
– Supply Voltage (RL=10[kΩ])

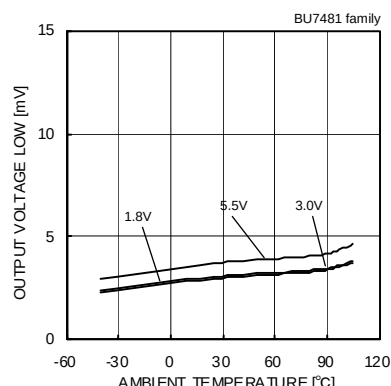


Fig.77
Output Voltage Low – Ambient
Temperature (RL=10[kΩ])

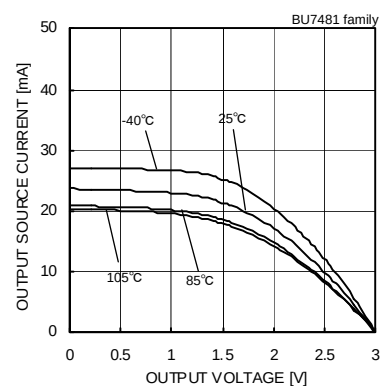


Fig.78
Output Source Current – Output
Voltage (VDD=3[V])

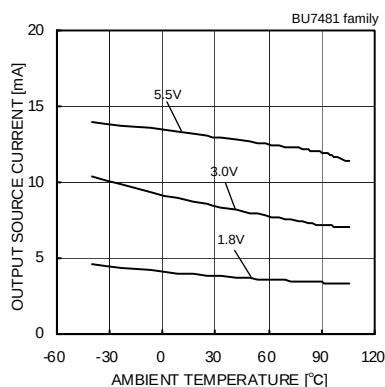


Fig.79
Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

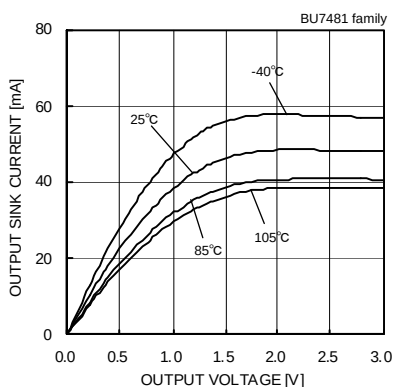


Fig.80
Output Sink Current – Output Voltage
(VDD=3[V])

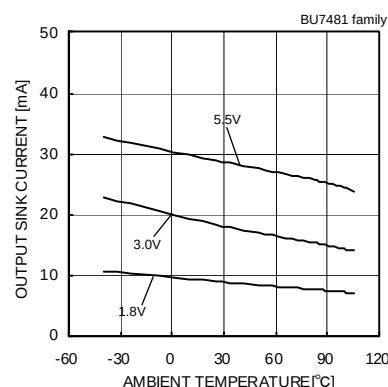


Fig.81
Output Sink Current – Ambient Temperature
(VOUT=VSS+0.4[V])

(*)The above data is ability value of sample, it is not guaranteed. BU7481G: -40[°C] ~ +85[°C] BU7481SG: -40[°C] ~ +105[°C]

●Reference Data (BU7481 family)

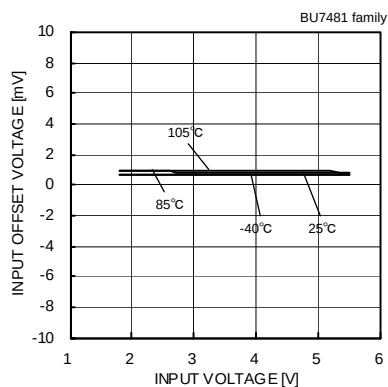


Fig.82
Input Offset Voltage – Supply Voltage
($V_{icm}=V_{DD}-1.2[V]$, $V_{OUT}=1.5[V]$)

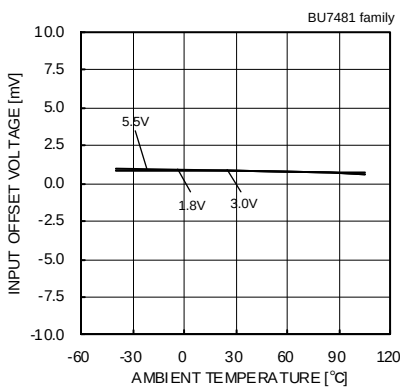


Fig.83
Input Offset Voltage – Ambient Temperature
($V_{icm}=V_{DD}-1.2[V]$, $V_{OUT}=1.5[V]$)

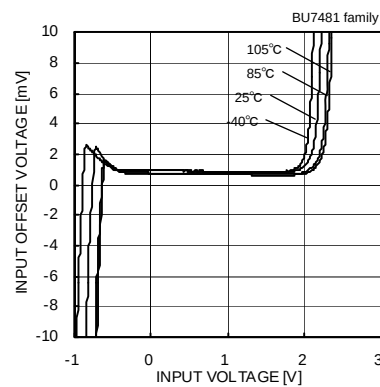


Fig.84
Input Offset Voltage – Input Voltage
($V_{DD}=3[V]$)

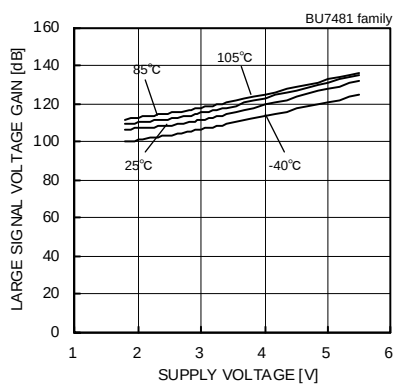


Fig.85
Large Signal Voltage Gain
– Supply Voltage

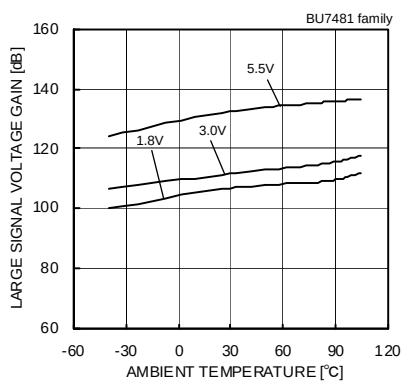


Fig.86
Large Signal Voltage Gain
– Ambient Temperature

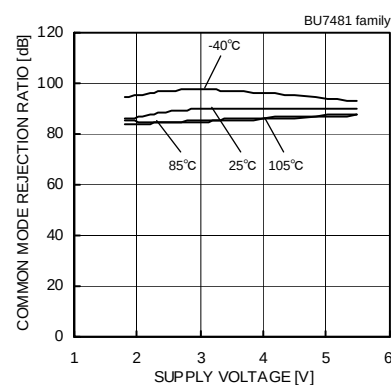


Fig.87
Common Mode Rejection Ratio
– Supply Voltage ($V_{DD}=3[V]$)

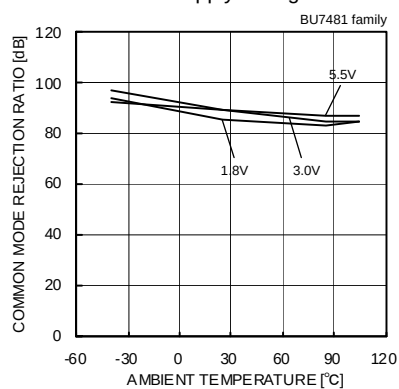


Fig.88
Common Mode Rejection Ratio
– Ambient Temperature

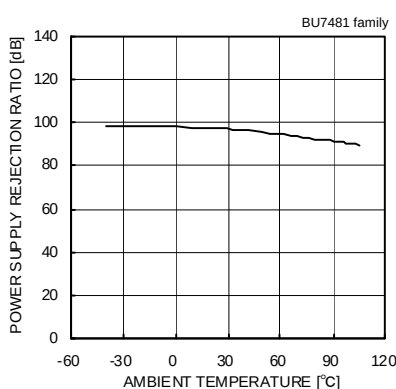


Fig.89
Power Supply Rejection Ratio
– Ambient Temperature

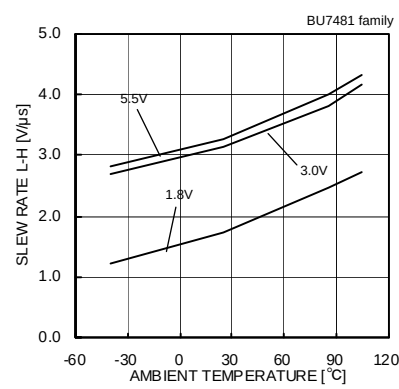


Fig.90
Slew Rate L-H
– Ambient Temperature

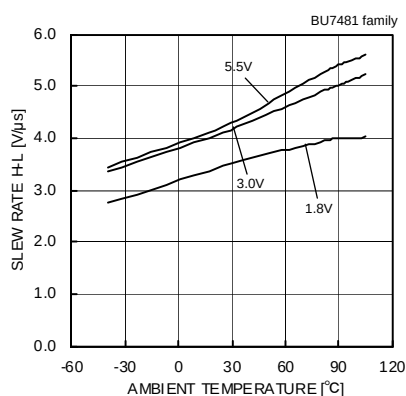


Fig.91
Slew Rate H-L – Ambient Temperature

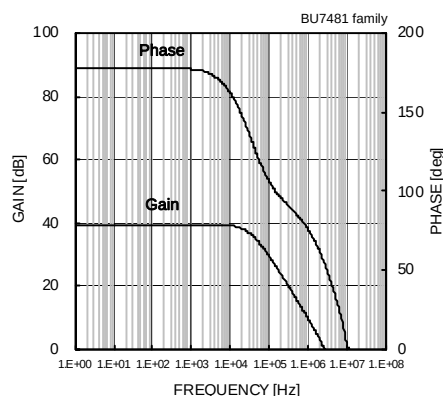


Fig.92
Voltage Gain—Frequency

(*)The above data is ability value of sample, it is not guaranteed. BU7481G: -40[°C] ~ +85[°C] BU7481SG: -40[°C] ~ +105[°C]

●Reference Data (BU7485 family)

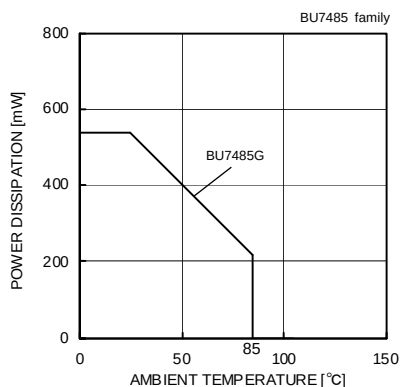


Fig.93
Derating curve

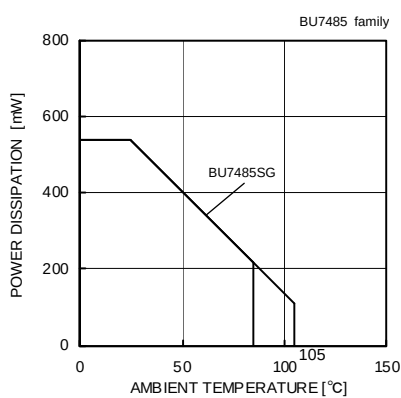


Fig.94
Derating curve

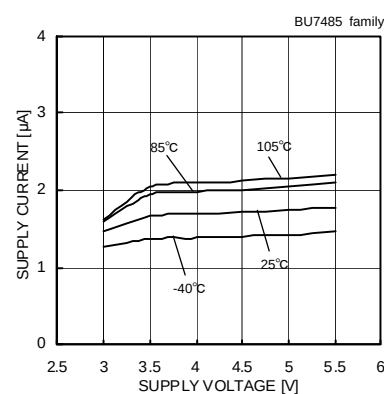


Fig.95
Supply Current – Supply Voltage

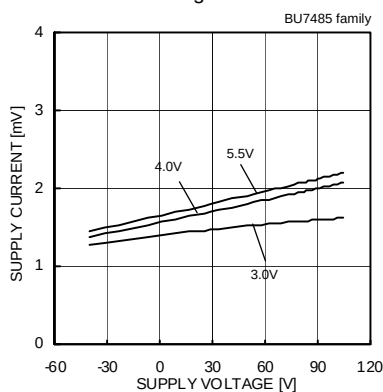


Fig.96
Supply Current
– Ambient Temperature

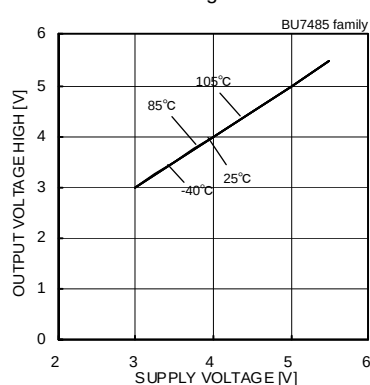


Fig.97
Output Voltage High
– Supply Voltage (RL=10[kΩ])

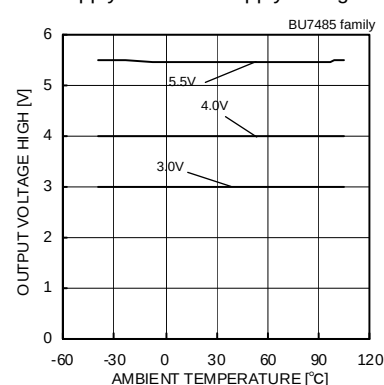


Fig.98
Output Voltage High
– Ambient Temperature (RL=10[kΩ])

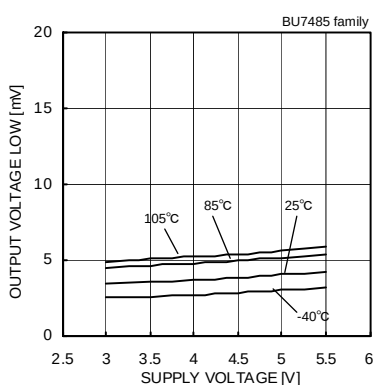


Fig.99
Output Voltage Low
– Supply Voltage (RL=10[kΩ])

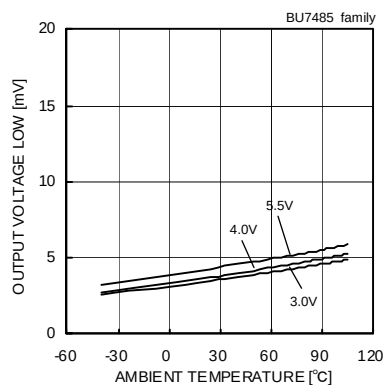


Fig.100
Output Voltage Low
– Ambient Temperature (RL=10[kΩ])

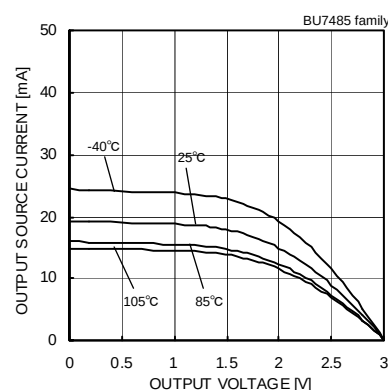


Fig.101
Output Source Current
– Output Voltage (VDD=3[V])

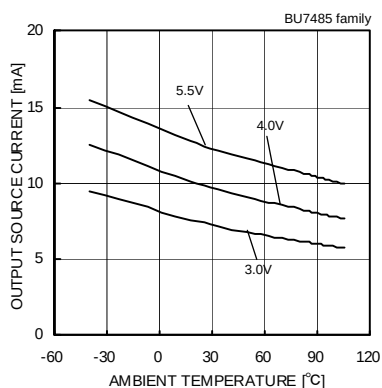


Fig.102
Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

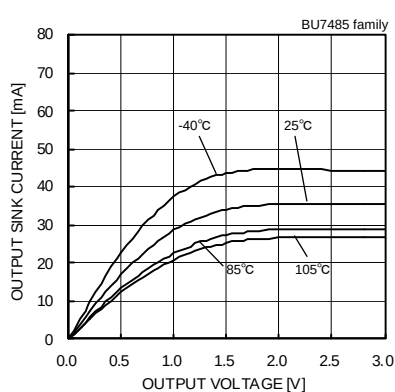


Fig.103
Output Sink Current – Output Voltage
(VDD=3[V])

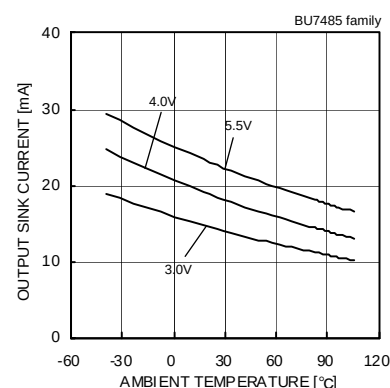


Fig.104
Output Sink Current – Ambient Temperature
(VOUT=VSS+0.4[V])

(*)The above data is ability value of sample, it is not guaranteed. BU7485G: -40[°C] ~ +85[°C] BU7485SG: -40[°C] ~ +105[°C]

●Reference Data (BU7485 family)

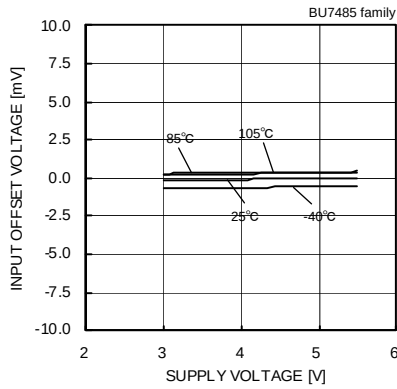


Fig.105

Input Offset Voltage – Supply Voltage
($V_{icm}=V_{DD}-1.4[V]$, $V_{OUT}=1.5[V]$)

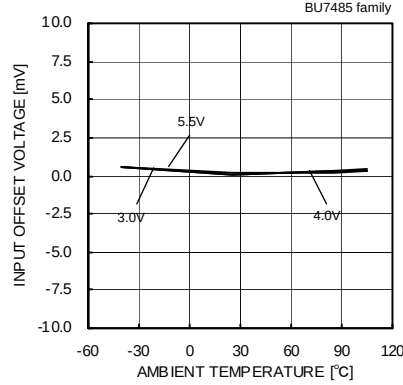


Fig.106

Input Offset Voltage – Ambient Temperature
($V_{icm}=V_{DD}-1.4[V]$, $V_{OUT}=1.5[V]$)

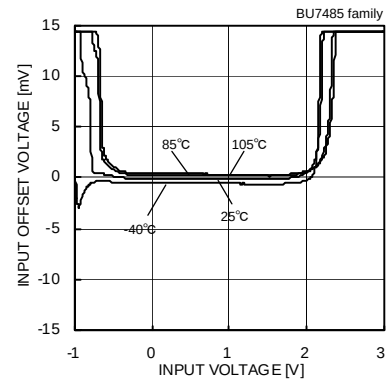


Fig.107

Input Offset Voltage – Input Voltage
($V_{DD}=3[V]$)

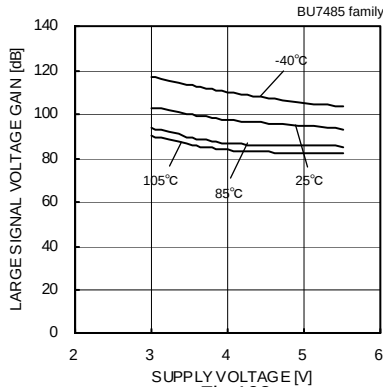


Fig.108

Large Signal Voltage Gain
– Supply Voltage

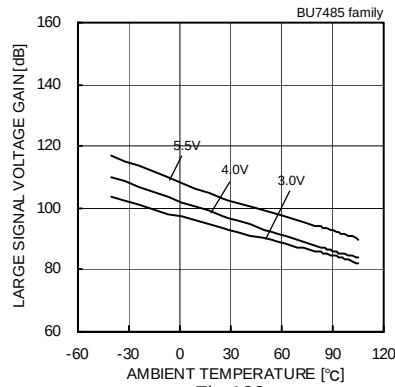


Fig.109

Large Signal Voltage Gain
– Ambient Temperature

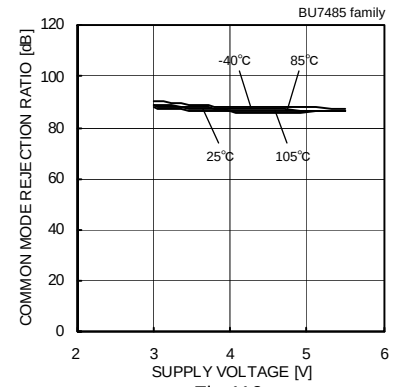


Fig.110

Common Mode Rejection Ratio
– Supply Voltage ($V_{DD}=3[V]$)

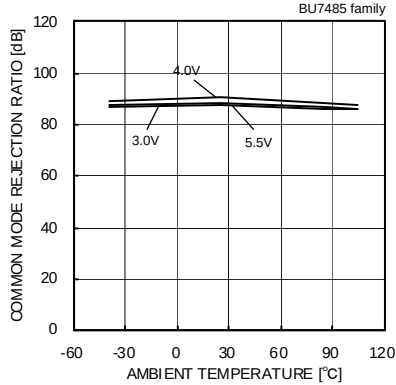


Fig.111

Common Mode Rejection Ratio
– Ambient Temperature

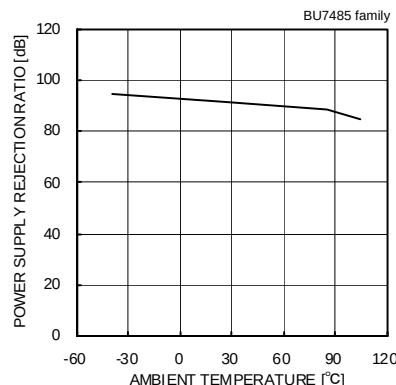


Fig.112

Power Supply Rejection Ratio
– Ambient Temperature

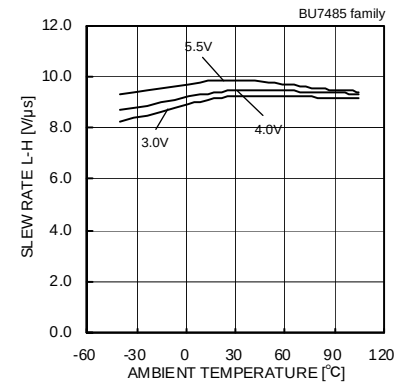


Fig.113

Slew Rate L-H
– Ambient Temperature

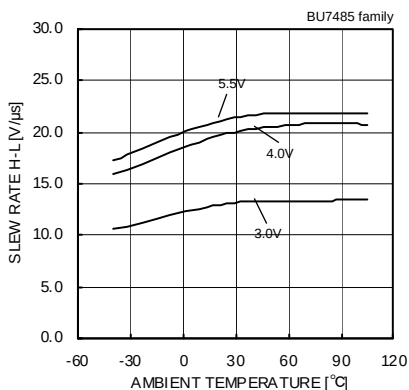


Fig.114

Slew Rate H-L – Ambient Temperature

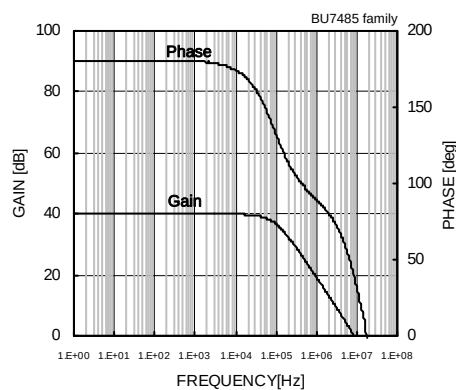


Fig.115

Voltage Gain – Frequency

(*)The above data is ability value of sample, it is not guaranteed. BU7485G: -40[°C] ~ +85[°C] BU7485SG: -40[°C] ~ +105[°C]

●Reference Data (BU5281 family)

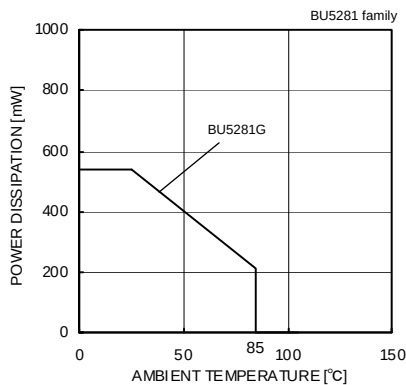


Fig.116
Derating curve

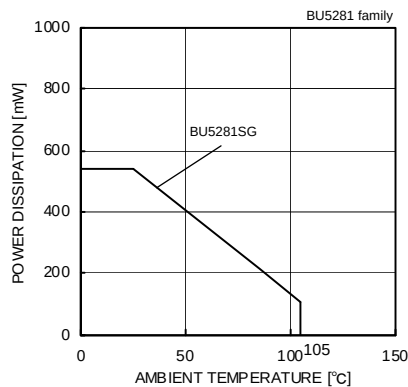


Fig.117
Derating curve

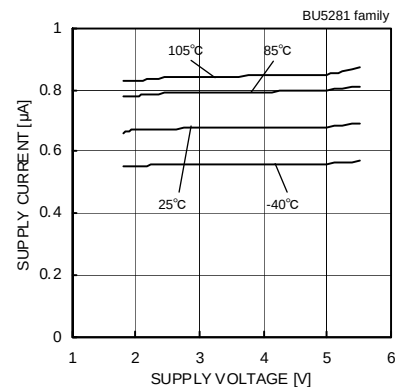


Fig.118
Supply Current – Supply Voltage

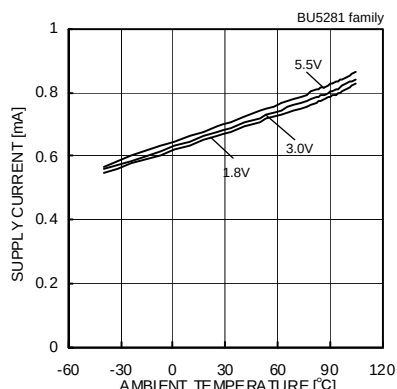


Fig.119
Supply Current
– Ambient Temperature

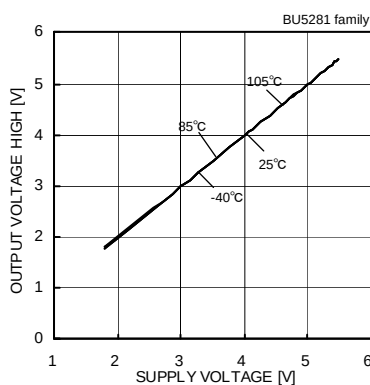


Fig.120
Output Voltage High
– Supply Voltage (RL=10[kΩ])

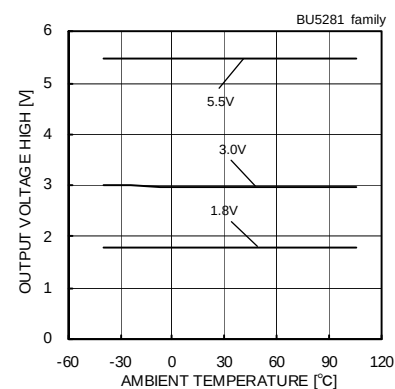


Fig.121
Output Voltage High
– Ambient Temperature (RL=10[kΩ])

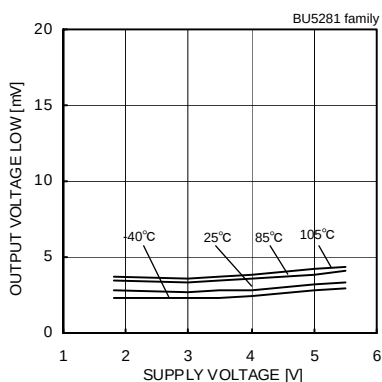


Fig.122
Output Voltage Low
– Supply Voltage (RL=10[kΩ])

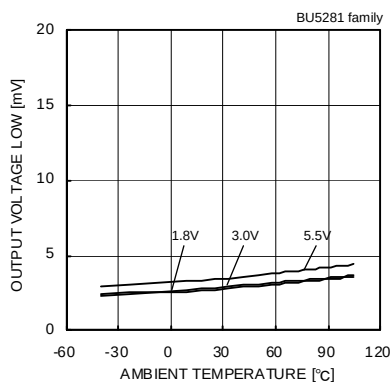


Fig.123
Output Voltage Low
– Ambient Temperature (RL=10[kΩ])

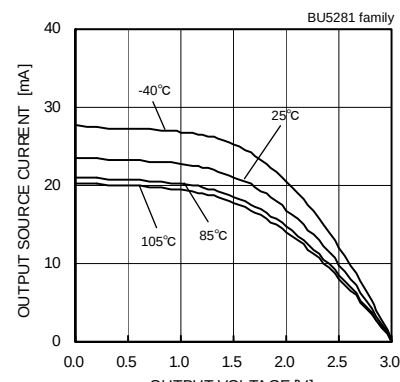


Fig.124
Output Source Current
– Output Voltage (VDD=3[V])

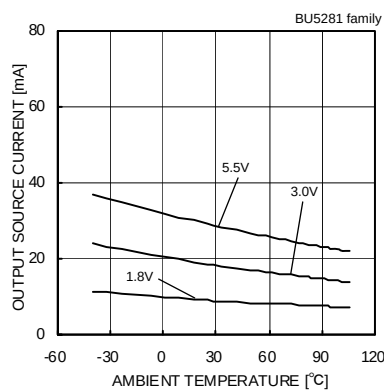


Fig.125
Output Source Current – Ambient Temperature
(VOUT=VDD-0.4[V])

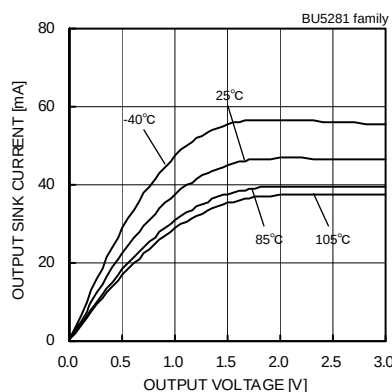


Fig.126
Output Sink Current – Output Voltage
(VDD=3[V])

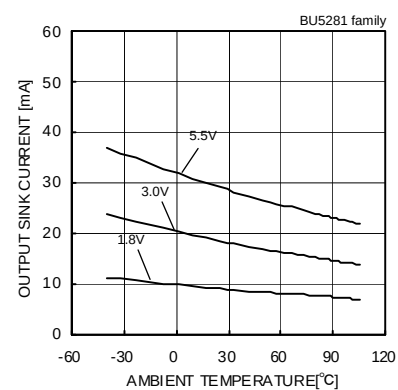


Fig.127
Output Sink Current – Ambient Temperature
(VOUT=VSS+0.4[V])

(*)The above data is ability value of sample, it is not guaranteed. BU5281G: -40[°C] ~ +85[°C] BU5281SG: -40[°C] ~ +105[°C]

●Reference Data (BU5281 family)

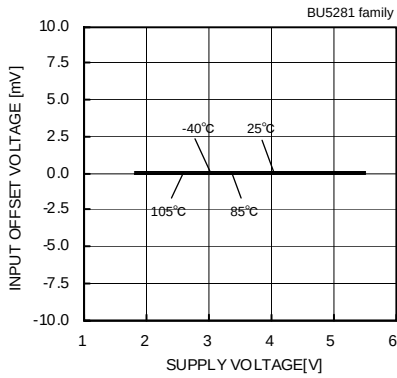


Fig.128
Input Offset Voltage – Supply Voltage
($V_{icm}=V_{DD}-1.2[V]$, $V_{OUT}=1.5[V]$)

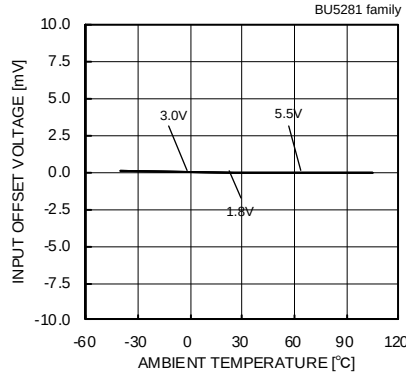


Fig.129
Input Offset Voltage – Ambient Temperature
($V_{icm}=V_{DD}-1.2[V]$, $V_{OUT}=1.5[V]$)

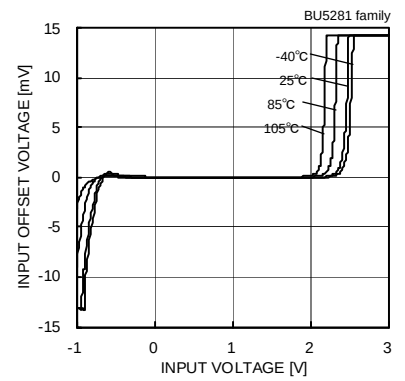


Fig.130
Input Offset Voltage – Input Voltage
($V_{DD}=3[V]$)

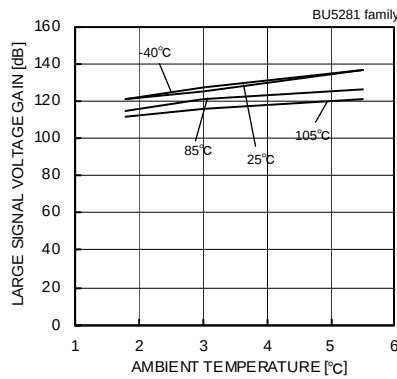


Fig.131
Large Signal Voltage Gain
– Supply Voltage

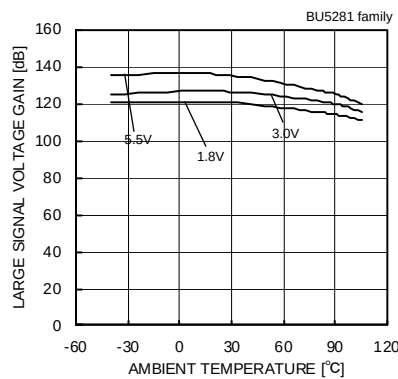


Fig.132
Large Signal Voltage Gain
– Ambient Temperature

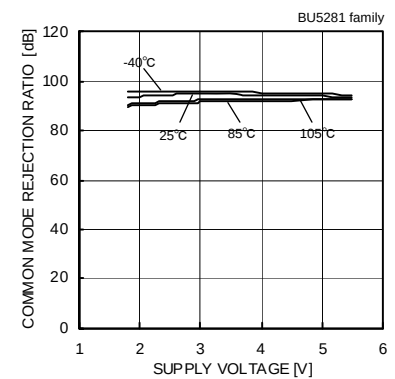


Fig.133
Common Mode Rejection Ratio
– Supply Voltage ($V_{DD}=3[V]$)

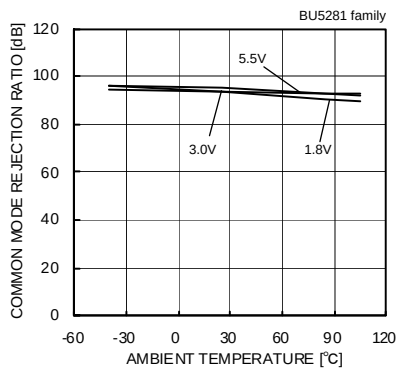


Fig.134
Common Mode Rejection Ratio
– Ambient Temperature

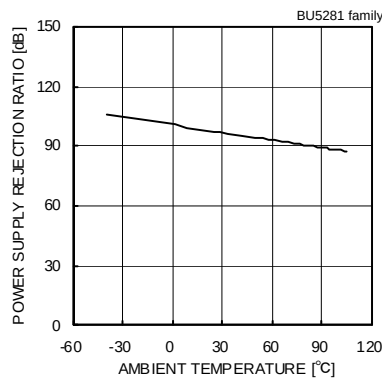


Fig.135
Power Supply Rejection Ratio
– Ambient Temperature

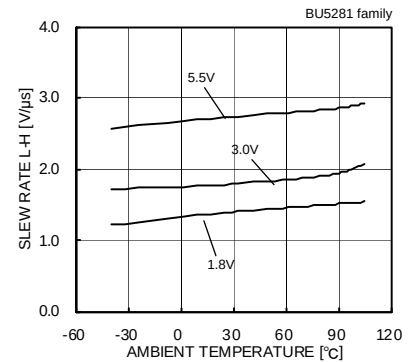


Fig.136
Slew Rate L-H –
Ambient Temperature

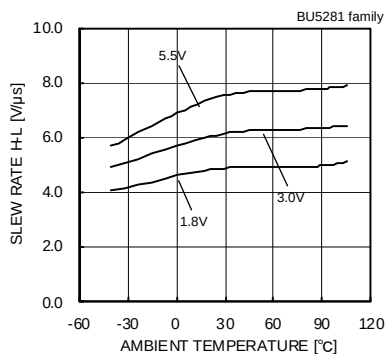


Fig.137
Slew Rate H-L – Ambient Temperature

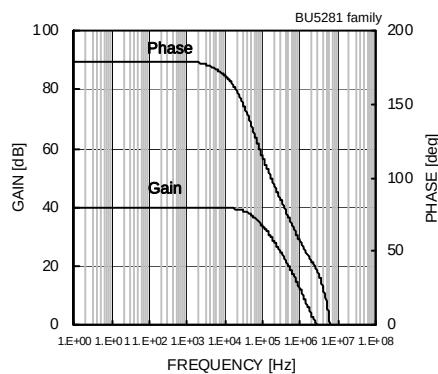


Fig.138
Voltage Gain – Frequency

(*)The above data is ability value of sample, it is not guaranteed. BU5281G: -40[°C] ~ +85[°C] BU5281SG: -40[°C] ~ +105[°C]

● Test circuit 1 NULL method

○ Input-Output Full Swing BU7291/BU7255 family

VDD, VSS, EK, Vicm Unit:[V]

Parameter	VF	S1	S2	S3	VDD	VSS	EK	Vicm	Calculation
Input Offset Voltage	VF1	ON	ON	OFF	3	0	-1.5	3	1
Large Signal Voltage Gain	VF2	ON	ON	ON	3	0	-0.5	1.5	2
	VF3						-2.5		
Common-mode Rejection Ratio (Input Common-mode Voltage Range)	VF4	ON	ON	OFF	3	0	-1.5	0	3
	VF5						-1.5	3	
Power Supply Rejection Ratio	VF6	ON	ON	OFF	2.4	0	-1.2	0	4
	VF7				5.5				

○ Ground Sense BU7495/BU7481/BU7485/BU5281 family

VDD, VSS, EK, Vicm Unit:[V]

Parameter	VF	S1	S2	S3	VDD	VSS	EK	Vicm	Calculation
Input Offset Voltage	VF1	ON	ON	OFF	3	0	-1.5	1.8	1
Large Signal Voltage Gain	VF2	ON	ON	ON	3	0	-0.5	0.9	2
	VF3						-2.5		
Common-mode Rejection Ratio (Input Common-mode Voltage Range)	VF4	ON	ON	OFF	3	0	-1.5	0	3
	VF5						-1.5	1.8	
Power Supply Rejection Ratio	BU7495/BU7481/BU5281	ON	ON	OFF	1.8	0	-0.9	0	4
	BU7485				3.0				
	VF7				5.5				

— Calculation —

1. Input Offset Voltage (Vio)

$$V_{io} = \frac{|VF1|}{1+R_f/R_s} \quad [V]$$

2. Large Signal Voltage Gain (Av)

$$A_v = 20 \log \frac{2 \times (1+R_f/R_s)}{|VF2-VF3|} \quad [dB]$$

3 Common-mode Rejection Ratio (CMRR)

$$CMRR = 20 \log \frac{\Delta V_{icm} \times (1+R_f/R_s)}{|VF4-VF5|} \quad [dB]$$

4. Power Supply Rejection Ratio (PSRR)

$$PSRR = 20 \log \frac{\Delta V_{DD} \times (1+R_f/R_s)}{|VF6-VF7|} \quad [dB]$$

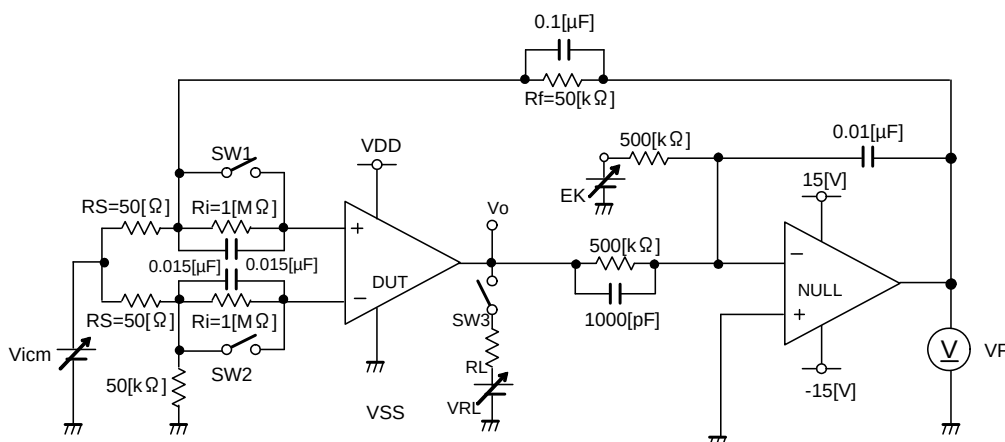


Fig.139 Test circuit 1 (one channel only)

●Test circuit 2 switch condition

SW No.	SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7	SW 8	SW 9	SW 10	SW 11	SW 12
Supply Current	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage (RL=10[kΩ])	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF
Output Current	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF
Slew Rate	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	ON
Maximum Frequency	ON	OFF	OFF	ON	ON	OFF	OFF	OFF	ON	OFF	OFF	ON

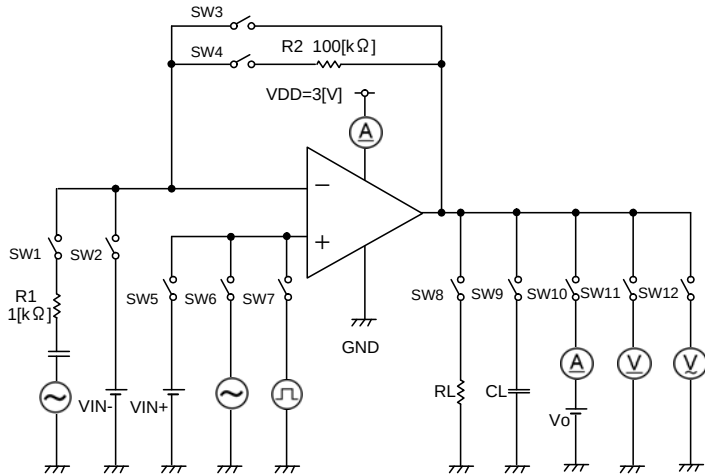


Fig.140 Test circuit 2

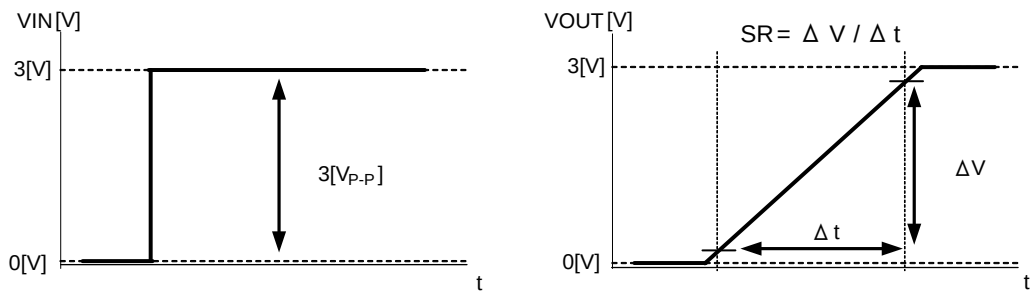


Fig.141 Slew rate input output wave
(Input-Output Full Swing BU7291/BU7255 family)

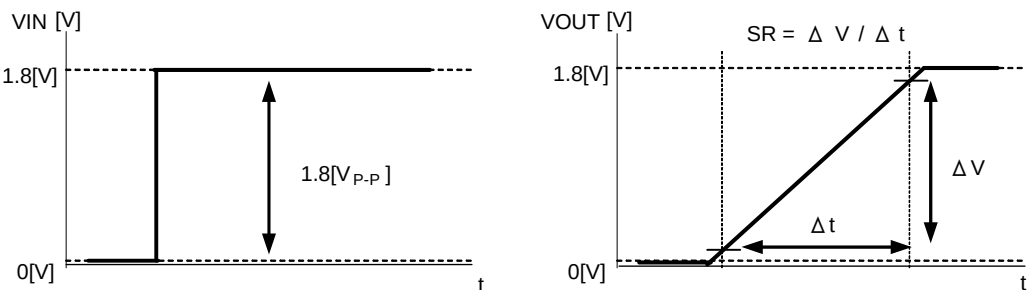


Fig.142 Slew rate input output wave
(Ground Sense BU7495/BU7481/BU7485/BU5281 family)

●Test circuit 3 Channel Separation

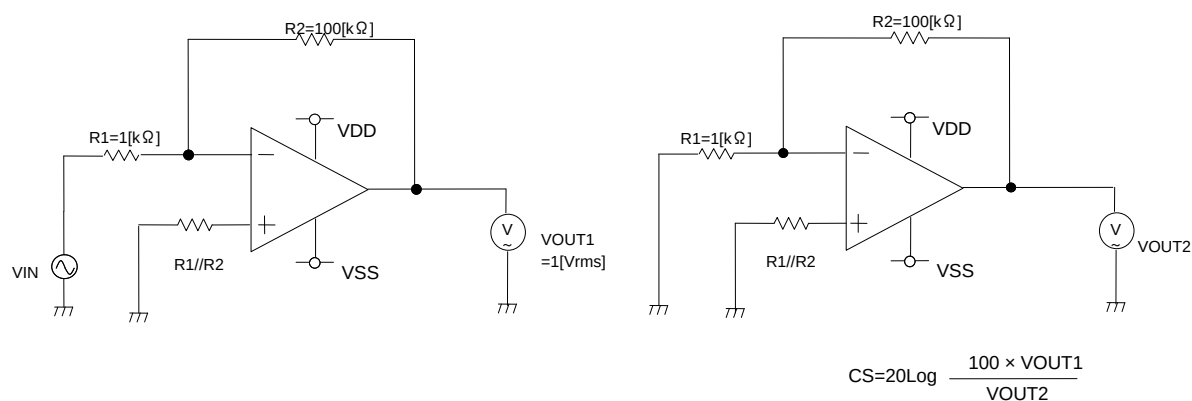


Fig.143 Test circuit 3

●Schematic Diagram

○Input-Output Full Swing BU7291/BU7255 family

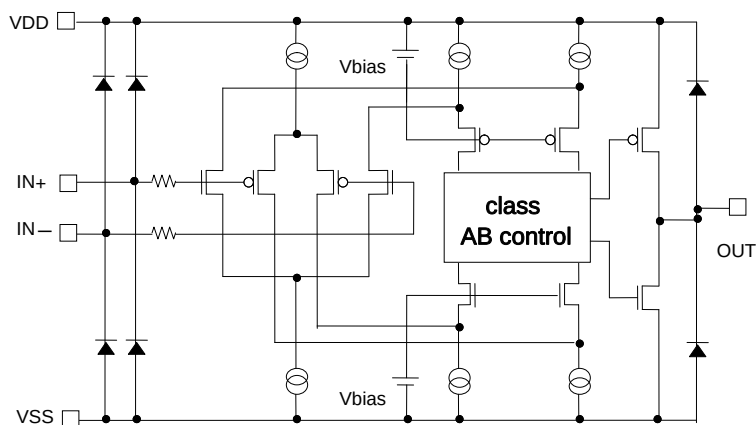


Fig.144 Input-Output Full Swing Schematic Diagram

○Ground Sense BU7495/BU7481/BU7485/BU5281 family

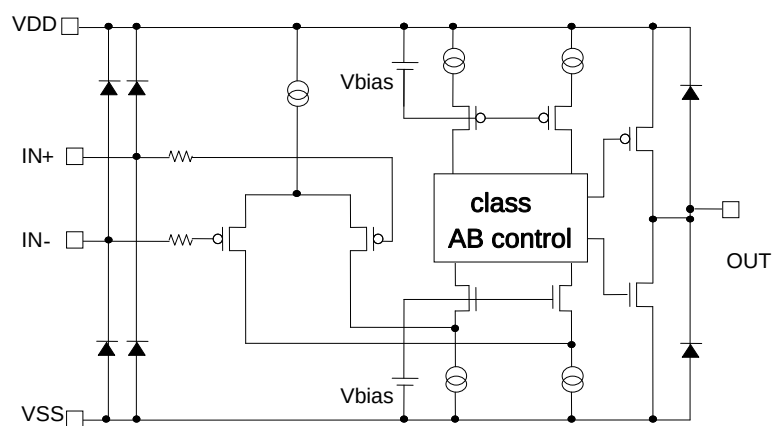


Fig.145 Ground Sense Schematic Diagram

●Examples of circuit

○Voltage follower

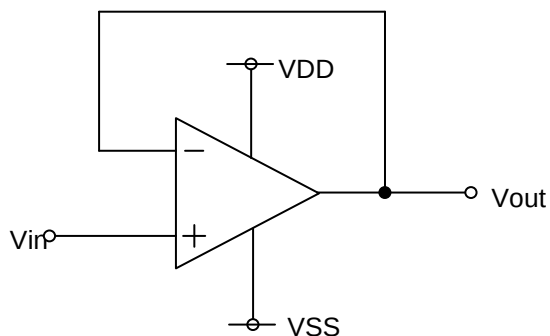


Fig.146 Voltage follower

Voltage gain is 0 [dB].

This circuit controls output voltage (V_{out}) equal input voltage (V_{in}), and keeps V_{out} with stable because of high input impedance and low output impedance.

V_{out} is shown next formula.

$$V_{out} = V_{in}$$

○Inverting amplifier

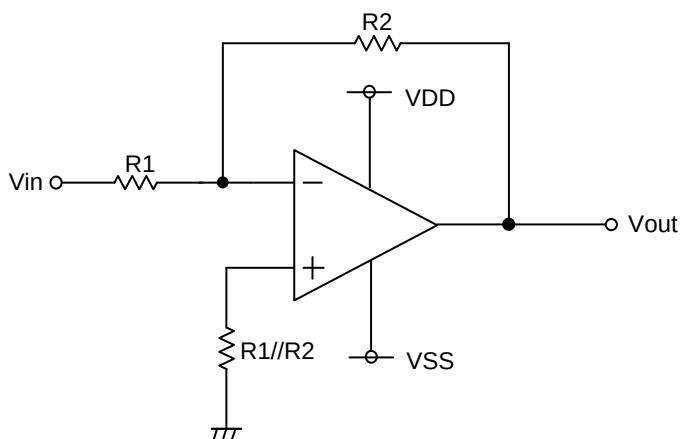


Fig.147 Inverting amplifier circuit

For inverting amplifier, V_{in} is amplified by voltage gain decided R_1 and R_2 , and phase reversed voltage is outputted. V_{out} is shown next formula.

$$V_{out} = -(R_2/R_1) \cdot V_{in}$$

Input impedance is R_1 .

○Non-inverting amplifier

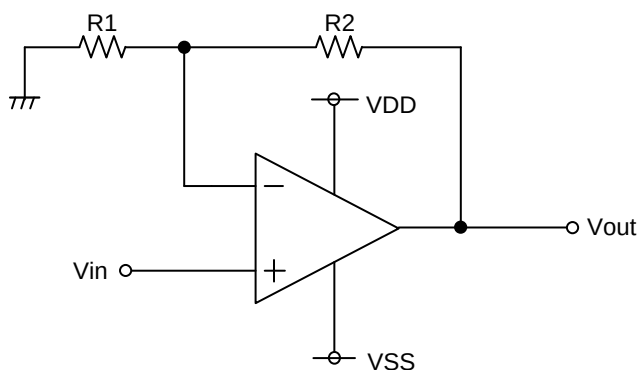


Fig.148 Non-inverting amplifier circuit

For non-inverting amplifier, V_{in} is amplified by voltage gain decided R_1 and R_2 , and phase is same with V_{in} .

V_{out} is shown next formula.

$$V_{out} = (1 + R_2/R_1) \cdot V_{in}$$

This circuit realizes high input impedance because Input impedance is operational amplifier's input Impedance.

●Derating Curve

Power dissipation (total loss) indicates the power that can be consumed by IC at $T_a=25^{\circ}\text{C}$ (normal temperature). IC is heated when it consumed power, and the temperature of IC chip becomes higher than ambient temperature. The temperature that can be accepted by IC chip depends on circuit configuration, manufacturing process, and consumable power is limited. Power dissipation is determined by the temperature allowed in IC chip (maximum junction temperature) and thermal resistance of package (heat dissipation capability). The maximum junction temperature is typically equal to the maximum value in the storage package (heat dissipation capability). The maximum junction temperature is typically equal to the maximum value in the storage temperature range. Heat generated by consumed power of IC radiates from the mold resin or lead frame of the package. The parameter which indicates this heat dissipation capability (hardness of heat release) is called thermal resistance, represented by the symbol θ_{ja} [$^{\circ}\text{C}/\text{W}$]. The temperature of IC inside the package can be estimated by this thermal resistance.

Fig.149 (a) shows the model of thermal resistance of the package. Thermal resistance θ_{ja} , ambient temperature T_a , junction temperature T_j , and power dissipation P_d can be calculated by the equation below:

$$\theta_{ja} = (T_j - T_a) / P_d \quad [^{\circ}\text{C}/\text{W}] \quad \dots \dots (I)$$

Derating curve in Fig.149 (b) indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient is determined by thermal resistance θ_{ja} . Thermal resistance θ_{ja} depends on chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Fig.150(c)-(d) show a derating curve for an example of BU7291 family, BU7255 family, BU7495 family, BU7481 family, BU7485 family, BU5281 family.

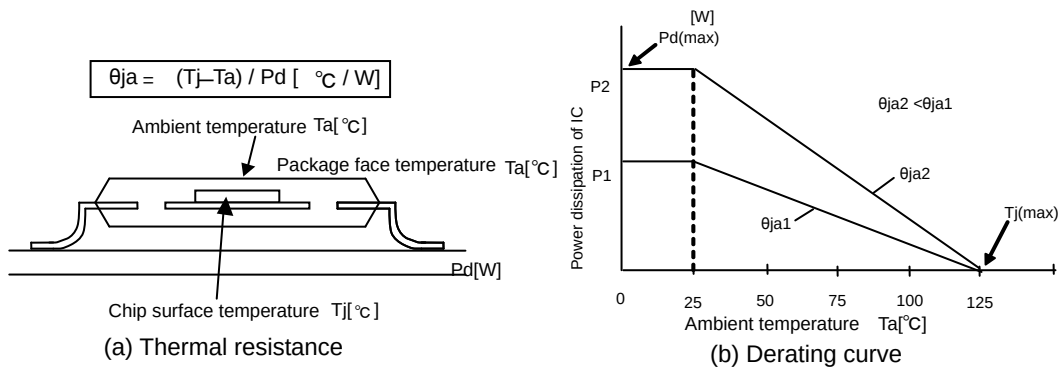
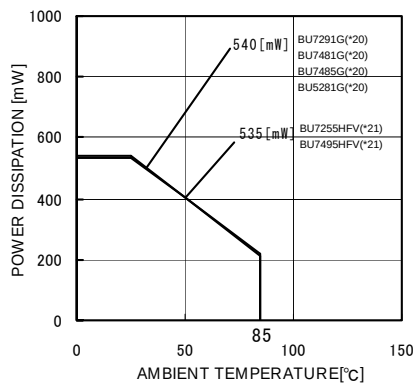
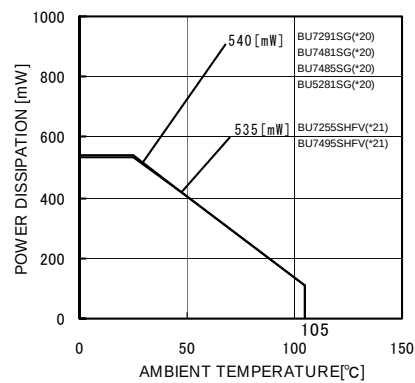


Fig.149 Thermal resistance and derating



(c) BU7291G BU7481G BU7485G
BU5281G BU7255HFV BU7495HFV



(d) BU7291SG BU7481SG BU7485SG
BU5281SG BU7255SHFV BU7495SHFV

(*20)	(*21)	Unit
5.4	5.35	[mW/°C]

When using the unit above $T_a=25^{\circ}\text{C}$, subtract the value above per degree $^{\circ}\text{C}$. Permissible dissipation is the value when FR4 glass epoxy board 70[mm] × 70[mm] × 1.6[mm] (copper foil area below 3[%]) is mounted

Fig.150 Derating Curve

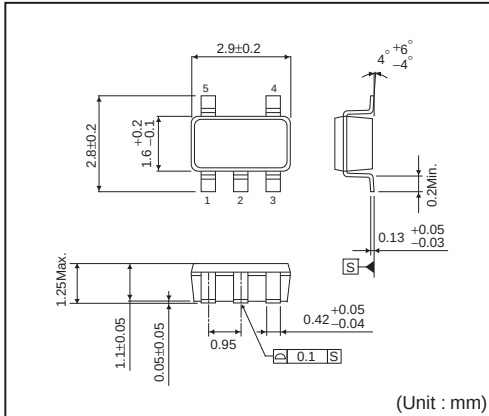
●Notes for Use

- 1) Absolute maximum ratings
Absolute maximum ratings are the values which indicate the limits, within which the given voltage range can be safely charged to the terminal. However, it does not guarantee the circuit operation.
- 2) Applied voltage to the input terminal
For normal circuit operation of voltage comparator, please input voltage for its input terminal within input common mode voltage $V_{DD} + 0.3[V]$. Then, regardless of power supply voltage, $V_{SS}-0.3[V]$ can be applied to input terminals without deterioration or destruction of its characteristics.
- 3) Operating power supply (split power supply/single power supply)
The operational amplifier operates if a given level of voltage is applied between V_{DD} and V_{SS} . Therefore, the operational amplifier can be operated under single power supply or split power supply.
- 4) Power dissipation (P_d)
If the IC is used under excessive power dissipation. An increase in the chip temperature will cause deterioration of the radical characteristics of IC. For example, reduction of current capability. Take consideration of the effective power dissipation and thermal design with a sufficient margin. P_d is reference to the provided power dissipation curve.
- 5) Output short circuit
If short circuit occurs between the output terminal and V_{DD} terminal, excessive in output current may flow and generate heat, causing destruction of the IC. Take due care.
- 6) Using under strong electromagnetic field
Be careful when using the IC under strong electromagnetic field because it may malfunction.
- 7) Usage of IC
When stress is applied to the IC through warp of the printed circuit board, The characteristics may fluctuate due to the piezo effect. Be careful of the warp of the printed circuit board.
- 8) Testing IC on the set board
When testing IC on the set board, in cases where the capacitor is connected to the low impedance, make sure to discharge per fabrication because there is a possibility that IC may be damaged by stress. When removing IC from the set board, it is essential to cut supply voltage. As a countermeasure against the static electricity, observe proper grounding during fabrication process and take due care when carrying and storage it.
- 9) The IC destruction caused by capacitive load
The transistors in circuits may be damaged when V_{DD} terminal and V_{SS} terminal is shorted with the charged output terminal capacitor. When IC is used as an operational amplifier or as an application circuit, where oscillation is not activated by an output capacitor, the output capacitor must be kept below $0.1[\mu F]$ in order to prevent the damage mentioned above.
- 10) Decoupling capacitor
Insert the decoupling capacitance between V_{DD} and V_{SS} , for stable operation of operational amplifier.
- 11) Latch up
Be careful of input voltage that exceed the V_{DD} and V_{SS} . When CMOS device have sometimes occur latch up operation. And protect the IC from abnormaly noise.

●Ordering Part Number

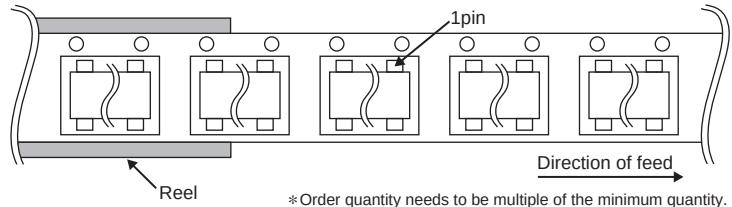
B	U	7	4	9	5	S	H	F	V	-	T	R
Part No.		Part No.					Package			Packaging and forming specification		
		Input-Output Full Swing					G: SSOP5			TR: Embossed tape and reel		
		Ground Sense					HFV: HVSOF5					
		7291 , 7291S , 7255 , 7255S										
		7495 , 7495S , 7481 , 7481S										
		7485 , 7485S , 5281 , 5281S										

SSOP5

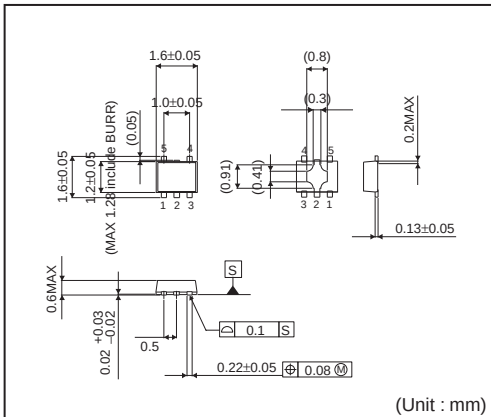


<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)

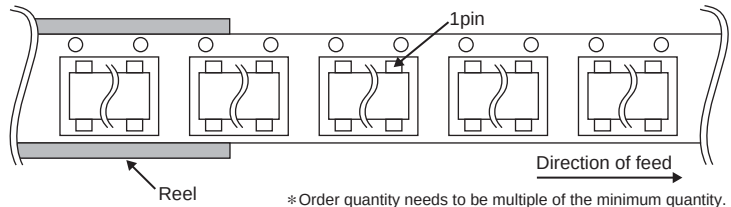


HVSOF5



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR (The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand)



Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - Installation of protection circuits or other protective devices to improve system safety
 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
 - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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